

ATX Version 3.0 Multi Rail Desktop Platform Power Supply

Design Guide

Revision 2.0

February 2022

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Revision History

Document Number	Revision Number	Description	Revision Date
	0.5	Initial release of combined power supply design guide Combined CFX12V, LFX12V, ATX12V, SFX12V, and TFX12V content into one desktop power supply design guide CFX12V content derived from revision 1.2 Updated 12V1 current for 300 W configuration Updated efficiency loading for 300 W configuration LFX12V content derived from revision 1.1 ATX12V content derived from revision 2.2 SFX12V content derived from revision 3.1 TFX12V content derived from revision 2.1 Updated 12V1 current for 300 W configuration Updated efficiency loading for 300 W configuration Updated Capacitive Load section to use standard capacitor values Updated 5 VSB efficiency recommendations for Digital Office platforms Removed power-down warning from power supply timing diagram	January 2006
336521	1.0	Marked sections with labels to indicate REQUIRED, RECOMMENDED, or OPTIONAL items Added 12V2 Current for Processor Configurations table	June 2006
		Added revision numbers to form factor specific chapters	
	1.1	 Removed outdated ENERGY STAR* requirements and added some new ENERGY STAR information. Updated Typical Power Distribution tables for all power supply form factors and updated minimum loads. Updated cross regulation figures. Added Flex ATX power supply form factor. Updated capacitive loading table. Clarified over voltage and over current verbiage. Added Power-up Cross Loading Condition section. Other changes shown in red with change bars. 	March 2007
	1.2	 Section 4.3.1 and Added max of 400 mV Ripple/Noise to PS_ON and PWR_OK signals Section 14.2 Figure 49 replaced to implement change in dimension C Section 4.3 Added Power-down timing to Figure 4-3 and Table 4-9: Power Supply TimingTable 4-9 (T6 > 1 ms) Section 8.3 Clarified Class D requirements. Added additional references for EMC requirements by country Section 4.5.9 Added Climate Savers Computing text Updated all Cross-regulation graphs 	February 2008



Document Number	Revision Number	Description	Revision Date
		• Section 2 updated configuration charts	
		Removed dates from reference documentation. Refer to the latest version available	
		• Updated Figure 58	
	1.3	Updated Section <u>4.2.3</u> Remote sensing to recommended level	July 2012
		Added Section <u>4.2.10</u> 12 V2DC Minimum Loading Recommendation	
		Added Section 4.4.2 +5 VSB Fall time Recommendation	
		Updated Section 4.2.9 Voltage Hold-up Time	
		• Updated Section 4.5.9 Overall Power Supply Efficiency and ENERGY STAR	
		Changed Floppy Drive Connector to OPTIONAL level	
		Changed Section <u>5.2.2.6</u> Serial ATA Connectors to Required level	
		Update <u>Table 2-1</u> : 12V2 Current for Processor Configurations	
		• Updated <u>Table 4-2</u> : DC Output Voltage Regulation -12V to recommended level	
		• Updated <u>Table 4-5</u> : Recommended System DC and AC power consumption	
		Updated Table 4-9 Power Supply Timing recommended value	
		• Updated <u>Table 4-15</u> : Efficiency versus Load	
	1.31	Updated Table 4-5 Recommended System DC and AC power consumption	April 2013
		Changed Section 4.2.10 12 V2DC Minimum Loading to REQUIRED	
		Updated Section 4.3.6 Rise Time	
		• Updated	
		CFX12V Specific Guidelines to version 1.5	
		 LFX12V Specific Guidelines to version 1.3 	
		ATX12V Specific Guidelines to version 2.4	
		— SFX12V Specific Guidelines to version 3.3	
		— TFX12V Specific Guidelines to version 2.4	
		Flex ATX Specific Guidelines to version 1.1	
	1.4	• Updated Section <u>1.2</u> , <u>Table 1-1</u> with new terminology	June 2017
		 Updated Section <u>2.1</u> peak and sustain current requirements 	
		• Updated Section 3.1 Table 4-1 – removed current values in table	
		• Updated Section 4.2.2, Table 4-3 – 12V1 and 12V2 new step size, added 12V3/4 step size	
		Updated Section 4.2.4 - low power 5VSB efficiency	
		• Updated Section 4.2.6, Table 4-7 – Decoupling cap values were changed	
		Added Figure 4-2 in Section 4.2.8	



Document Number	Revision Number	Description	Revision Date
		Updated Section 4.2.10, Table 4-8 – 12V2 recommendation is now required	
		 Updated Section 4.3, Table 4-9 now shows T0, Timing requirements T1 and T3 added for ALPM and note about timing requirements in the year 2020 	
		Updated Section 4.3.4 to provide recommendation to increase current on 5VSB for computers with ALPM	
		Added Figure 4-6 in section 4.3.6 for more clarity	
		Updated Section 4.4.2 5VSB fall time as recommendation and loading conditions used in the test plan	
		• Re-wrote Section 4.5.8 for overall efficiency targets – Added Section about Low Load Condition	
		Re-wrote Section 4.5.9 to include Efficiency recommendations for current Energy Regulations	
		 Updated Section <u>5.1</u> to include labeling instructions for which DG timings are supported by the PSU 	
		• Updated Section 5.2.2.3 Floppy Drive Connector to be reference only	
		Added Section 5.2.2.4 for PCIe* AIC connectors	
		• Updated Section 5.2.2.4.2, added Table 5-5 +12V power 8 pin connector pin out	
		Updated Section 6.1 – Acoustic note about acoustic targets can be customer specific	
		• Sections <u>11</u> , <u>12</u> , <u>13</u> , <u>14</u> , <u>15</u> and 16 Added form factor revision summary to beginning of each form factor specific section	
		Added new Intel Test Plan Section	
	1.41	• Update Section 2.1 – <u>Table 2-1</u> for 12V2 Processor sustain and peak power updates	October 2017
		 Added Section 2.2 for HEDT processors support 	
		• Updated Section 4.5.8 and added Table 4-14	
		• Update Section <u>4.3</u> – add note for T3	
		Update Section 4.5.9 – for ENERGY STAR* Computers Version 7.0	
		• Updated Chapters <u>11</u> , <u>12</u> , <u>13</u> , <u>14</u> , <u>15</u> , and <u>16</u>	
		CFX12V Specific Guidelines to version 1.61 LFX12V Specific Guidelines to version 1.41 ATX12V Specific Guidelines to version 2.51 SFX12V Specific Guidelines to version 3.41 TFX12V Specific Guidelines to version 2.51 Flex ATX Specific Guidelines to version 1.21	
		• Updated Test Plan Sections 16.2.1 and Table 16-2 - 12V2 load table - to match <u>Table 2-1</u>	
		• Updated Test Plan Sections 16.2.2 and Table 16-3 for new 95W load of 21A Continuous	
		Updated Test Plan Sections 16.3.3 and Table 16-10 – added 12W load level	
		Updated Test Plan Section 16.6 to include mention of PSU for new CPU TDP levels mentioned in Section 2.1	



Document Number	Revision Number	Description	Revision Date
	1.42	Update <u>Table 2-1</u> : 12V2 Current for Processor Configurations.	May 2018
		Update Figure 4-3: Power Supply Timing.	
		• Add Figure 4-5: +5VSB Power on timing versus VAC.	
		 Add note Table 5-10: Serial ATA* Power Connector Pin- out: +3.3V is removed from SATA V3.2 spec. 	
		• Updated Chapters <u>11</u> , <u>12</u> , <u>13</u> , <u>14</u> , <u>15, and 16</u>	
		CFX12V Specific Guidelines to version 1.62 LFX12V Specific Guidelines to version 1.42 ATX12V Specific Guidelines to version 2.52 SFX12V Specific Guidelines to version 3.42 TFX12V Specific Guidelines to version 2.52 Flex ATX Specific Guidelines to version 1.22	
		• Remove Test Plan Section. Refer to Document #338448 for test plan.	
		Add Section 10.2 Reliability – PS_ON# toggle for S0ix mode.	
	1.43	• Update <u>Table 2-1</u> : 12V2 Current for Processor Configurations.	March 2019
		• Change -12VDC capacitive load from 3300uF to 330uF.	
		• Updated Chapters <u>11</u> , <u>12</u> , <u>13</u> , <u>14</u> , <u>15</u> and 16	
		CFX12V Specific Guidelines to version 1.63 LFX12V Specific Guidelines to version 1.43 ATX12V Specific Guidelines to version 2.53 SFX12V Specific Guidelines to version 3.43 TFX12V Specific Guidelines to version 2.53 Flex ATX Specific Guidelines to version 1.23	
		Update Table 4-5 5VSB efficiency	
	1.43.01	Updated <u>Table 2-1</u> to correct the 12V2 peak current requirement of 165W.	May 2020
		 Changed the Section <u>1.1</u> topic to "Alternative Low Power Mode" for Power Supplies. 	
		 Added PSU Addendum for all future processor support in Section 2.1. 	
		• Updated Section <u>4.5.9</u> to support Energy Star v8.	
	2.0	• Updated text for clarity in <u>Chapter 1</u> : Introduction	February
		Added Section 1.1	2022
		Added second reference for ALPM in Section 4.3.3	
		Added new Reference Documentations to list in <u>Section</u>	
		1.2 -	
		 Updated <u>Table 2-1</u> and reference text for Processors Updated Section 2.2 to provide clarity 	
		Added ALL of <u>Chapter 3</u> – PCIe* Add-in Card Consideration	
		Updated <u>Section 4.2.1</u> and <u>Table 4-2</u> : DC Output Voltage Regulation— +12V Voltage range changed	
		Updated <u>Table 4-3</u> - DC Voltage step size modified for 12V2 & 12V3/4.	



Document Number	Revision Number	Description	Revision Date
		Added <u>Table 4-4</u> : DC Output Transient Slew Rate and text describing Slew Rate	
		Updated <u>Table 4-9</u> : Power Supply Timing – Previous Required value is now Legacy Timings and Previous Recommended is now Required.	
		Updated <u>Section 4.3.3</u> – to include mention response to PS_ON# changes beyond 100 ms	
		• Simplified <u>Table 4-14</u> : Low Load Efficiency Requirements	
		 Added mention for label of all PSUs should state revision of the specification that it meets and 12VHPWR label for power level supported in <u>Section 5.1</u> – 	
		Added PCIe* Graphics Card Connector section increased detail for all 3 connector options including new 12VHPWR connector in <u>Section 5.2.2.4</u> –	
		 Changed table at beginning of each section to represent new mechanical size Specification Revision in <u>Chapter 11</u>, 12, 13, 14, 15, and 16 	

§§



1 Introduction

This document aligns to ATX Specification Version 3.0

This document provides design suggestions for various power supply form factors. The power supplies are primarily intended for use with desktop system designs. It should not be inferred that all power supplies must conform exactly to the content of this document, though there are key parameters that define mechanical fit across a common set of platforms. Since power supply needs vary depending on system configuration, the design specifics described are not intended to support all possible systems. The REQUIRED sections are intended to be followed for all systems. The RECOMMENDED sections could be modified based on system design. Lastly, a few sections are labeled as OPTIONAL, which would not be intended for all design but is helpful to some designs.

1.1 Alternative Low Power Mode for Power Supplies

Computers continue to change and introduce new power states. One of these new power states is generically called an Alternative Low Power Mode (ALPM). Some examples of Alternative Low Power Modes are Microsoft* Windows* 10 Modern Standby* or Google* Chrome* Lucid Sleep. These new power states have created requirements for power supplies. Below is a summary of these requirements as they are mentioned throughout the document.

- <u>Section 4.2.4</u> Other Lower Power System Requirements:

 <u>Table 4-5</u> shows that ALPM requirements are at the 0.55 A and 1.5 A load levels.
- <u>Section 4.3</u> Timing, Housekeeping and Control:
 <u>Table 4-9</u> has a column for require values of T1 and T3 to support ALPM.
- <u>Section 4.2.2</u>-Reliability PS_ON# Toggle for S0ix Mode and <u>Section 10.2</u>:
 The number of times a PSU toggles on and off is expected to increase.
- <u>Section 4.3.3:</u> PS_ON# REQUIRED
 PSU response quickly to toggling of PS_ON# signal.

1.2 Reference Documentation

The following documents are referenced in various sections of this design guide. The document may not be up to date; refer to the latest version. For guidelines not specifically mentioned here, refer to the appropriate document.

Document	Document Number /Source
European Association of Consumer Electronics Manufacturers (EACEM*)	AB13-94-146
Hazardous Substance List / Certification	



Document	Document Number /Source
IEEE* Recommended Practice on Surge Voltages in Low-Voltage AC Circuits	ANSI* C62.41-1991
IEEE Guide on Surge Testing for Equipment Connected to Low-Voltage AC Power Circuits	ANSI C62.45-1992
Nordic national requirement in addition to EN 60950	EMKO-TSE (74-SEC) 207/94
American National Standard for Methods of Measurement of Radio- Noise Emissions from Low-Voltage Electrical and Electronic Equipment in the Range of 9 kHz to 40 GHz for EMI testing	ANSI C63.4
UL 60950-1 First Edition –CAN/CSA-C22.2 No. 60950-1-03 First Edition, IEC 60950-1: 2001 + Amendments and National Deviations, EN 60950-1: 2001 + Amendment A11: EU Low Voltage Directive (73/23/EEC) (CE Compliance) GB-4943 (China) CNS 14336: (Taiwan BSMI) FCC*, Class B, Part 15 (Radiated and Conducted Emissions) CISPR* 22 / EN55022, 5th Edition (Radiated and Conducted Emissions) EN55024 (ITE Specific Immunity) EN 61000-4-2 – Electrostatic Discharge EN 61000-4-3 – Radiated RFI Immunity EN 61000-4-6 – RF Conducted EN 61000-4-6 – RF Conducted EN 61000-4-11 – Voltage Dips, Short Interrupts and Fluctuations EN61000-3-2 (Harmonics) EN61000-3-3 (Voltage Flicker) EU EMC Directive ((8/9/336/EEC) (CE Compliance)) IEC 62368	
PCI Express* Card Electromechanical Specification Revision 5.0	PCISIG.com Doc # 15904
PCI Express* Card Electromechanical (CEM) Engineering Change Notice (ECN) – "Power Excursion Limits for 300-600w PCIe* AICs"	PCISIG.com Doc # 16495
PCI Express* Card Electromechanical (CEM) Engineering Change Request (ECR) – "Power Excursion Limits for up to 300 W PCIe* AICs"	PCISIG.com Doc # 16680



Document	Document Number /Source
ENERGY STAR for Computers Version 8.0	https://www.energystar .gov/products/spec/co mputers version 8 0 pd
European Union Energy Related Products(ErP) Lot 6	https://ec.europa.eu/en ergy/en/topics/energy- efficiency/energy- efficient- products/standby
Power Supply Efficiency Labeling Program – 80 plus Organization	80plus.org
Generalized Test Protocol for Calculating the Energy Efficiency of Internal Ac-Dc and Dc-Dc Power Supplies Revision 6.7.1	EPRI – Listed at 80plus.org website
Efficiency (ETA) and Noise (LAMBDA) programs: Cybenetics LTD	Cybenetics.com

1.3 Terminology

 $\underline{\text{Table 1-1}}$ defines the acronyms, conventions, and terminology that is used throughout the design guide.

Table 1-1: Conventions and Terminology

Acronym, Convention/ Terminology	Description
ALPM	Alternative Low Power Mode, ALPM replaces the traditional Sleep Mode (ACPI S3) with a new sleep mode. An example of ALPM is with Microsoft* Windows Modern Standby* or Lucid Sleep with Google* Chrome*.
AWG	American Wire Gauge
ВА	Declared sound power, LwAd. The declared sound power level shall be measured according to ISO* 7779 for the power supply and reported according to ISO 9296.
CFM	Cubic Feet per Minute (airflow).
Monotonically	A waveform changes from one level to another in a steady fashion, without oscillation.
MTBF	Mean time between failure.
Noise	The periodic or random signals over frequency band of 0 Hz to 20 MHz.
Non-ALPM	Computers that do not use Alternative Low Power Mode use traditional Sleep Mode (ACPI S3).
Overcurrent	A condition in which the current demand on a supply output exceeds its rated output current. This commonly occurs if there is a "short circuit" condition in the load attached to the supply.



Acronym, Convention/ Terminology	Description
PFC	Power Factor Correction.
р-р	Peak-to-Peak Voltage Measurement.
PWR_OK	PWR_OK is a "power good" signal used by the system power supply to indicate that the +5VDC, +3.3 VDC and +12VDC outputs are above the under-voltage thresholds of the power supply.
Ripple noise	The periodic or random signals over a frequency band of 0 Hz to 20 MHz.
Rise Time	Rise time is defined as the time it takes any output voltage to rise from 10% to 90% of its nominal voltage.
Surge	The condition where the AC line voltage rises above nominal voltage.
VSB or Standby Voltage	An output voltage that is present whenever AC power is applied to the AC inputs of the supply.

Table 1-2: Support Terminology

Category	Description
Optional	The status given to items within this design guide, which are not required to meet design guide, however, some system applications may optionally use these features. May be a required or recommended item in a future design guide.
Recommended	The status given to items within this design guide, which are not required to meet design guide, however, are required by many system applications. May be a required item in a future design guide.
Required	The status given to items within this design guide, which are required to meet design guide and a large majority of system applications.

§§



2 Processor Configurations

2.1 Processor Configurations - RECOMMENDED

The processor power in a desktop computer is provided by the 12V2 power rail of power supplies with multiple power rails. To meet the desktop processor power needs a desktop power supply must provide the current value list in <u>Table 2-1</u> for the 12V2 voltage rail. <u>Table 2-1</u> shows the various processor current requirements represented by the desktop processor's TDP. If a power supply only has one 12V rail then <u>Table 2-1</u> shows the amount of current that needs to be dedicated to the desktop processor in a system level power budget.

Table 2-1: 12V2 Current for Processor Configurations

PSU 12V2 Capability Recommendations			
Processor TDP Continuous Current			
165 W	37.5 A	40 A	
125 W	26 A	39 A	
65 W	23 A	34 A	
35 W	11 A	19 A	

NOTES:

- 1. If the power supply supports, the 240 VA Energy Hazard protection requirement then current levels for the 12 Volt rail above 18 Amps must be split into multiple 12 V rails.
- Continuous current is defined for the processors PL2 (Turbo) power limit since desktop processors are expected to stay at PL2 for many seconds, sometimes close to 1 minute. For a PSU any time over 1 second is considered Continuous current.
- 3. Peak Current is defined for the processor's PL4 which defines Peak current for a max time of 10 ms.

All future processor power/PSU current requirements will be defined in a document titled *ATX12VO* and *ATX12V* PSU Design Guide Addendum (# 621484) that is applicable to both Single Rail and Multi Rail ATX Power Supplies. Refer to that document for details of where these values come from.

2.2 High End Desktop Market Processor Considerations

The High-End Desktop market requires power supplies with higher power levels than typical mainstream market. The EPS12V specification is often referenced for these designs. The EPS12V specification is a power supply form factor for the server market. This Desktop ATX Power Supply Design Guide includes higher power levels to support these higher performance desktop computers.



2.2.1 Modular Power Supply Connectors

A modular power supply, with multiple detachable cable options is recommended to provide the greatest flexibility to the end user. This approach reduces the chassis volume consumed by unused power cables to improve cable routing and cooling.

The dedicated 12V CPU connectors on the motherboard are either a single 8 pin (2x4) connector, or one or two 4 pin (2x2) connectors, detailed in Section 5.2.2.5 + 12 V Power Connector. These are often referenced as EPS12V connectors.

<u>Section 5.2.2.4</u> *PCI-Express (PCIe*) Add-in Card Connector* details three cable/connector options to deliver +12 V power rails to a PCIe* Add-in Card. While each of the three connectors provides a 12V rail to power the chassis component, they use different pin locations and mechanical keying, and are not directly interchangeable. Therefore, a modular design is an option to support multiple end use configurations.

For example, the end user might require a power supply to support a system with a lower-power or non-overclocked CPU and multiple higher-power graphics cards and thus populate the PSU outputs with multiple power cables configured for the PCIe* graphics cards. Alternatively, a higher power overclocked CPU system mounting a single, lower power graphics card may require more 12V CPU power and a single plug for PCIe* power. A modular power supply allows connectors on the power supply to provide 12V power and then the end user can select the appropriately configured cable/plug to provide 12V power in their system with no change to the pinout of the PSU itself.

Three examples of modular designs are shown below. The orange box in each picture identifies the connectors on the power supply that provide 12V power rails.



18 AWG wire is typically used to meet the 6-8 Amp/pin requirements of most chassis components. (Example of an exception to this it the 12VHPWR connector that uses 16AWG wires.) Based on this example of 6-8 Amp/pin the following recommendation applies to how much power/current can be supported by each connector determined by the number of +12V pins included in that connector. Using Table 2-1, the number of pins and connectors for motherboard 12V CPU (EPS12V) connectors can be calculated.

- 12-16 A support for 2x2 (4pin) connector
- 18-24 A support for 2x3 (6pin) connector
- 24-32 A support for 2x4 (8pin) connector

A distinction must be made between the current per pin *available* at the PSU through a connector pin and 18 AWG wire vs. the maximum *demand* for current from the



connected chassis component such as a PCIe* Card or motherboard 12V CPU connector(s).

For example, a standard 2x3 PCIe* power connector supporting a graphics card will draw no more than 6.75 Amps total through its three power pins and two ground pins. Similarly, the 2x4 PCIe* power connector will draw no more than 13.5 Amps total through three power pins and three ground pins.

It is possible to reduce the number of conductors consumed at the PSU by providing the 12V to a 2x4 PCIe* card power connector through a 2x2 modular connector at the power supply, for example. Before reducing the conductor count, the PSU designer should also consider the copper losses and the resulting voltage drop incurred by the two cable connectors and a length of the 18 AWG conductor.

This recommendation is based on common design practice. The PSU and system designer may deviate from this guidance but remains responsible for designing the PSU to meet all electrical, thermal, safety and reliability requirements based on the application of the PSU.

It is important to recognize that the new 600W 12VHPWR cable/plug introduced with PCIe* Gen 5.0 (detailed in Section 5.2.2.4.3), requires $\underline{16 \text{ AWG}}$ wire and a per-pin current capacity of $\underline{9.2 \text{ A}}$.

2.2.2 Overclocking Recommendations

The power levels listed in <u>Section 2.1</u> - Processor Configurations - RECOMMENDED are for processors that follow the Plan of Record (POR) power levels that include Turbo Mode. If the processor is overclocked, then power requirements will be increased. If the power supply is expected to support end users who intend to overclock then the 12V power rail to the processor should be higher than what is listed in <u>Table 2-1</u>: 12V2 Current for Processor Configurations.

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3 PCI Express* Add-in Card Considerations

The PCI Express* (PCIe*) Card Electromechanical Specification (CEM Spec) provides thermal, power, mechanical, and signal integrity design guidance for the PCI Express* Add-in Card (AIC) form factor. This includes the card's electrical and mechanical interface with a host system board, chassis, and power supply.

The 5.0 Revision of the PCIe* spec introduces four significant updates that directly affect this power supply specification:

- 1. A Power Excursion allowance was introduced to support brief, high current demands on power, beyond the rated TDP.
- 2. The maximum power consumption for a single Add-in Card was doubled to 600 W. This is the per-card limit from all sources combined.
- 3. A new 48V (nominal) power rail was added.
- 4. Two new Auxiliary Power Connectors were introduced to provide the full 600 W on a single cable connector. The new 12VHPWR connector supports 600W on the 12V rail while the 48VHPWR provides 600W on the 48V rail. Four new sideband signal conductors permit simple signaling between the Add-in Card and power supply.

3.1 PCIe* Add-in Card Power Excursions

PCI Express* CEM specifications prior to Revision 5.0 did not provide any allowance to permit an Add-in Card to exceed the TDP power for its designated power range. This effectively limited the absolute power consumption of each Add-in Card to a hard limit such as 10 W, 75 W, 150 W, 225 W, or 300 W, even when it would be advantageous for it to make short-duration high-current demands on a power rail.

It is recognized that while many existing PCIe* CEM products already exceed the card power limits, in violation of prior PCIe* CEM specs, their power supplies were never explicitly designed to withstand these excursions. Consequently, power excursions beyond these limits, however brief, might cause unexpected card or system malfunctions, potentially triggering PSU overcurrent protection (OCP) or voltage droop. This risk increases when multiple PCIe* cards are installed in a system.

The PCIe* CEM 5.0 spec addresses the need for occasional power excursions by permitting the card to briefly exceed the existing limits on supply power while still abiding by the power limits on a time-averaged basis. This allows the power supply and Add-in Card to jointly withstand increased power demands with a limited duration and magnitude.

The PCIe* CEM 5.0 specification introduces the concept of *Sustained Power*, the average power delivered though a single power cable in a 1-second moving interval. This allows the card and power supply to operate within existing power and thermal envelopes, since the excursions' durations are very short and do not measurably increase the average temperature of any component.

These updates are described in an Engineering Change Notice (ECN) to the PCI Express* Card Electromechanical (CEM) Specification, Revision 5.0, and will be



integrated into the specification itself in upcoming releases. This ECN is titled "Power Excursion Limits for 300W-600W PCIe* AICs" (Doc# 16495). This ECN defines power excursions, which are a "temporary condition in which the power exceeds the maximum sustained power". The ECN states the purpose of the document is to "allow system designers to properly design power subsystems to enable these excursions". Based on this PCIe* ECN, this section of the ATX Power Supply Design Guide will provide guidance for power supplies to be designed to meet the permitted power excursions of PCIe* Add-in Cards.

Note that Add-in Cards with power from 300-600 watts did not exist prior to the PCIe* CEM 5.0 specification. Earlier generations of PCIe* Add-in Cards were limited to 300 Watts or below. While many of the relevant specification updates are duplicated here for convenience, designers should confirm that they have the most up to date information by consulting the reference documentation on https://www.pcisig.com. The information below is drawn from the PCIe* documentation at the time of publication of this document.

The power consumption excursions allowed in a PCIe* Add-in Card rated at 300 watts to 600 watts, only when the mount one of new 12VHPWR or 48VHPWR power connectors, also introduced in PCIe* CEM 5.0. The 48VHPWR connector is not relevant to this document and therefore will not be discussed further. Similar power excursions are not permitted for the legacy 2x3 and 2x4 PCIe* Auxiliary Power connectors since that would introduce backward compatibility risks with legacy power supplies.

A second Engineering Change Request, "Power Excursion Limits up to 300 Watts" is under consideration. This ECR would define similar power excursions for the 12VHPWR Auxiliary Power connector for cards less than 300 Watts. It is likely that an identical Power Excursion allowance will be adopted for Add-in Cards rated at 300 W or less, so power supply vendors are advised to provision any 12V rails supporting the 12VHPWR connector with support for Power Excursions at <u>all power levels</u>.

The power supply must be able to provide voltages that remain within the requirements defined in $\frac{\text{Table 4-2}}{\text{Table 4-2}}$ (Section $\frac{4.2}{\text{Ad}}$) during the defined power excursions. Add-in Card power consumption excursion limits are defined by the maximum ratio (R) of average power consumption in any continuous time interval (T) relative to the maximum sustained (average) power of that Add-in Card.

At all times, the Add-in Card must concurrently adhere to the power excursion limits for all time interval lengths as defined in <u>Table 3-1</u> and <u>Figure 3-1</u> as well as the rolling time average of the sustained power of the card. <u>Table 3-1</u> shows the power excursion limits for all time intervals in which "R" is calculated by dividing the average power consumption in a continuous time interval of length "T" but the maximum sustained power of that Add-in Card. The Add-in Card must also stay within all voltage tolerance and current as defined in <u>Section 3.2</u> and <u>Table 3-5</u>.

Table 3-1: PCI Express* CEM Add-in Card Power Excursion Limits Table 45

Average Power Calculation Interval Length in microseconds(µs) "T"	Ratio of Average Power1 in Interval "T" Divided by Maximum Sustain Power	Notes
≤ 100	3	2
>100 and <1,000,000 µs (1 sec)	4 - 0.2171 x ln(T)	3



Average Power Calculation Interval Length in microseconds(µs) "T"	Ratio of Average Power1 in Interval "T" Divided by Maximum Sustain Power	Notes
≥ 1,000,000 µs (1 sec)	1	-

NOTES:

- 1. $R = \frac{\text{average power during internal T}}{\text{Max Sustained Power (ie.TDP)}}$
- 2. This is also the max ratio of instantaneous power relative to maximum sustained power.
- 3. In() is the natural logarithm function.
- Add-in Card must at all times and concurrently adhere to power excursion limits for all time interval lengths as well as the limits defined for Power Supply Rail Requirements in <u>Table 3-5</u>.
- 5. Engineering Change Notice for up to 300 Watts (Work in Progress) will likely make this table apply to all cards mounting the 12VHPWR connector.

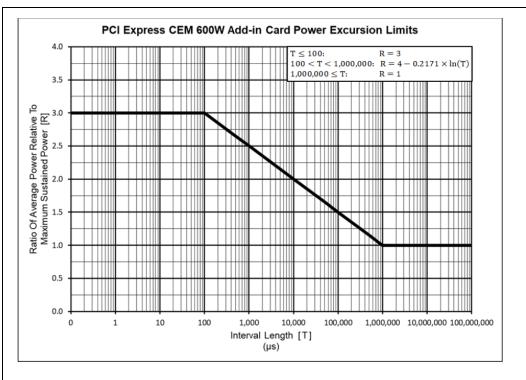


Figure 3-1: PCI Express* CEM Add-in Card Power Excursion Limits Chart

3.1.1 PCIe* Add-in Card and PSU Power Budgets

Three dominant power demands dictate the total system power provisioning:

- 1. CPU power consumption
- 2. PCIe Add-in Card power level



3. Rest-of-Platform power demand

Rest-of-Platform(ROP) collectively includes anything in a system (memory, storage, motherboard, peripherals, etc.) not including the PCIe Add-in Cards or CPU. Table 3-2 provides examples that generally balance these three power demands to obtain an overall PSU power rating. The PCIe power entries in the table are standard power levels for PCIe Add-in Cards defined in the PCIe CEM 5.0 Specification. As a consequence of the introduction of 450 W and 600 W Card power levels, the wide range of possible PCIe card power demands plays a dominant role in setting total platform power supply ratings.

These configurations will also serve as test cases for evaluating power supply excursions. The peak power demands of the PCIe Add-in Cards at each power level can guide the peak power demands of the PSU.

In cases where a PCIe Add-in Card has a sustained power not listed, use these values as a minimum value for all cards up to these power levels. The table below is seen as a minimum power level based on Rest of Platform (ROP) power. The ROP assumptions are shown in Table 3-2 below. If a system designer plans more ROP power, the overall platform power budget for a system must be increased. If a system designer plans less ROP power, then the PSU size can also decrease. In the case of ROP values lower than what is shown in Table 3-2, the calculations should be done for Peak Power Requirement for this specific system. If the Peak Power requirements for this specific system exceed the values shown in Table 3-3 than a PSU with support for higher peak power levels would be needed.

The CPU continuous power comes from $\underline{\text{Table 2-1}}$, taking the current value and multiplying by 11.2 Volts to create a power value and round up slightly. The CPUs used in these examples are the 65w TDP for the first row and 125w TDP for all other rows.

This is a recommendation for a Power Budget and guidance that is needed to define PSU Peak Power Excursion levels. These power budgets also assume only one PCIe Add-in Card will use these power excursions. If more than one PCIe Add-in Card is installed in the system, then the system designer needs to verify the power supply can provide enough power for all components in the system including the Peak Power Excursions of all components. This industry standard PSU Design Guide does not provide a standard definition for that type of system design.

Table 3-2: PCIe* AIC and PSU Power Budget used for Peak Power Excursion Test Cases

PCIe* AIC Power (W)	CPU Continuous Power (W)	Rest of Platform (W)	PSU Rated PSU Size (W)
75	275	100	450
150	300	100	550
225	300	125	650
300	300	150	750
450	300	250	1000
600	300	300	1200

• Rest of Platform power here will not apply to all systems.



- If Rest of Platform power is higher than what is in the table, increase the PSU size respectively.
- If Rest of Platform power is lower than what is listed in the table the PSU size can also be reduced, but Peak Power requirements are also expected to increase beyond what is listed in Table 3-3.
- CPU Power and Rest of Platform Power can vary from this table which would result in custom Peak Power requirements

3.1.2 PSU Power Excursion

Based on the power budgets in Table 3-2 and peak power of both the Processor detailed in <u>Table 2-1</u> and the PCIe* Add-in Cards in <u>Section 3.1</u>, the following Peak Power Requirements are defined for the Power Supply. The peak time for each power level is defined in <u>Table 3-3</u>. The PCIe Add-in cards power excursion are only designed for the new 12VHPWR connector, therefore the table is split into two different power levels where it is expected that power supplies greater than 450 watts will have at least one 12VHPWR connector.

Table 3-3: PCIe* AIC and PSU Power Budget used for Peak Power Excursion

Power Excursion % of PSU Rated Size PSU ≤ 450 Watts & PSUs without 12VHPWR Connector	Power Excursion % of PSU Rated Size PSU > 450 Watts & 12VHPWR Connector present	Time for Power Excursion (TE)	Testing Duty Cycle
100%	100%	Infinite	
110%	120%	100 ms	50%
135%	160%	10 ms	25%
145%	180%	1 ms	20%
150%	200%	100 μs	10%

NOTE: Peak Power defined in this table correspond to Platform Level Power Budgets described in Table 3-2 if CPU or Rest of Platform power is reduced from Table 3-2 to reduce PSU size, then custom Power Excursion % of PSU rated size must also be calculated.

The Testing Duty Cycle is not defined in the PCIe* CEM Gen 5.0 ECN, but it must be defined to create a test criteria specific to a power supply. The Testing Duty Cycle defines the percentage of time the Power Excursion value peaks with the remainder of the time defined as a Time_Constant (T_c). The Power Level defined is to have the RMS value during this Dynamic Load test to be the Rated Wattage of the Power Supply. Table 3-4_shows an example of how the testing criteria for power excursions of 1000 Watt Power Supply using an RMS value to average the rated power of a power supply. This calculation is the same as what is described in the PCIe* CEM Gen 5 Power Excursion ECN. For all power supplies with a rated wattage different than 1000 watts a similar RMS calculation needs to be performed.



Figure 3-2: Duty Cycle Definition

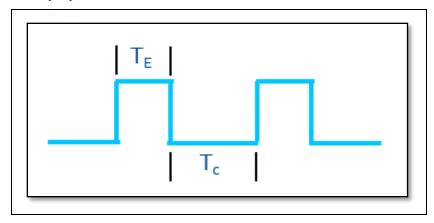


Table 3-4: Duty Cycle Example Test Criteria for a 1000W PSU - RMS

Duty Cycle	Time for Power Excursion (T _E)	Time Constant (T _C)	Power @ T _E	Power @ T _c
10%	100 µs	900 µs	2000 W	817 W
20%	1 ms	4 ms	1800 W	663 W
25%	10 ms	30 ms	1600 W	693 W
50%	100 ms	100 ms	1200 W	749 W

NOTES:

- 1. The Capacitive Load mentioned in <u>Table 4-7</u> is expected to be applied to this test scenario.
- 2. Total Test time for each Power Excursion testing time is expected to last until thermal saturation occurs in the PSU.
- 3. More details about test time for each row above and formulas to calculate T_C and T_E power values for different PSU sizes will be detailed in the "Desktop Platform Form Factor Power Supply Test Plan Doc #338448

3.2 PCIe* AIC Auxiliary Power Connectors

The PCIe CEM 5.0 specification defines three 12V Auxiliary Power Connectors to be used with PCIe Add-in Cards

- 1. 75 W 2x3 connector
- 0. 150 W 2x4 connector
- 1. 600 W 2x6 12VHPWR connector (new in PCIe 5.0)

<u>Section 5.2</u> specifies the Mechanical information for all DC Power Connectors. Note that the Voltage Tolerance listed below is different from this Power Supply Design Guide for the Low voltage tolerance <u>Table 4-2</u>, the reason for the difference is allowing for voltage drop on a motherboard from the Main Power Connector to the motherboard to the PCIe* Edge Card Connector. <u>Table 3-5</u> shows the voltage



tolerance required to the PCIe* Add-in Card at both the motherboard edge card connector and Auxiliary Power connectors. Each Auxiliary Power Connector must have voltage pins that belong to the same +12V power converter, if multiple voltage rails exist from the PSU.

Table 3-5: Auxiliary Power Connectors Power Supply Rail Requirements - +12V Only

+12V Power Rail Characteristic	2x3 Connector	2x4 Connector	12VHPWR Connector
Sustained Power ^{2, 4, 5}	75 Watts	150 Watts	600 Watts
+ 12 V Voltage Range	+5% / -8%	+5% / -8%	+5% / -8%
Current ^{3, 4, 5} (Max RMS)	6.75 Amps	13.5 Amps	55 Amps ¹

NOTES:

- 1. The maximum current slew rate for the 12VHPWR connector interface shall be no more than 5.0 A/ μ s.
- 2. Maximum sustained power is an average power in any continuous 1 second interval
- Maximum of root-mean-square (RMS) of current in any continuous 1 second interval
- 4. The main reference limit is the maximum allowed sustained power per connector and Add-in Card type. Add-in Card and System must concurrently comply with all power and voltage and current requirements in this table for the applicable connector and other requirements in this specification for the Add-in Card type.
- 5. Maximum instantaneous and other excursions exceeding these limits are defined in Section 3.1 of this document.

3.3 PCIe* Add-in Card Auxiliary Power Connectors Sideband Signals

The new 12VHPWR connector has 4 sideband signals defined that communicate between the Power Supply and the PCIe* Card. Two of these sideband signals are required with the connector and two of them are optional from the Power Supply. The four sideband signals are:

- SENSE0
- SENSE1
- CARD_PWR_STABLE
- CARD CBL PRES#

For the most up to date and detailed description, refer to <u>Section 5.3</u> – Optional Sideband Signal in the **PCI Express* Card Electromechanical Specification, Revision 5.0.** That document is available from <u>www.pcisig.com</u>.



3.3.1 Sense1 / Sense0 (Required)

These two sideband signals provide important information from the PSU to the Add-in Card and are therefore required from the power supply. These signals allow the PSU to tell the Add-in Card how much power the Add-in Card can use during both Initial Power Up and Maximum Permitted Power. In the PCI CEM Gen 5 spec these levels are called "Connector Initial Permitted Power" and "Connector Maximum Permitted Power" because they refer to the power limits that can be consumed thorough the Auxiliary Power Connector. The Maximum Permitted Power is the maximum supported by this auxiliary power connector alone. It does not correspond to power consumed through motherboard card edge connector.

The PSU providing the 12VHPWR auxiliary power connector must short the appropriate SENSE signals to ground or leave them open (high impedance) to indicate the power limits associated with the power supply. These SENSE signals must not change state while the Add-in Card is operational.

Support of the SENSE0/SENSE1 sideband signals is required for a PSU. Support for the SENSE0/SENSE1 sideband signals does not rely on any of the other optional sideband signals defined for the 12VHPWR connector.

Table 3-6: PCI Express* 12VHPWR Connector Power Limits

Sense0	Sense1	Initial Permitted Power at System Power Up	Maximum Sustain Power after Software Configuration
Gnd	Gnd	375 W	600 W
Open	Gnd	225 W	450 W
Gnd	Open	150 W	300 W
Open	Open	100 W	150 W

NOTE: If the Add-in Card does not monitor these signals, it must default to the lowest value in this table.

3.3.2 CARD_PWR_STABLE (Optional)

This optional sideband signal functions as a "Power Good" indicator from the Add-in Card to the PSU. When this signal is asserted, the Add-in Card is indicating that local power rails on the Add-in Card are within their operating limits. This signal can provide a fault detection from the Add-in Cards to the PSU, which can allow the PSU a protection opportunity.

If this signal is used by the PSU, the signal will come from the Add-in Card as an open collector / open-drain fashion. In the Add-in Card, this signal will be tied to a $100k\Omega$ pull-down resistor to ground. When implemented, the signal must be tied to a $4.7k\Omega$ pull-up resistor to +3.3V at the power supply. When the PSU or system monitors the state of the CARD_PWR_STABLE signal it must be done with a high impedance 3.3V logic compatible device input.



The Add-in Card will set this signal to Open (high impedance) whenever its local power rails that are critical to correct operation are within their operating limits. When the Add-in Card directly drives this signal low (0 / Ground), any of its local power rails are outside of their operating limits results in a fault for the Add-in Card. The Add-in Cards must drive this signal low for at least 100 ms or as long as the input power stays outside of the voltage specification detailed in Table 3-5: Auxiliary Power Connectors Power Supply Rail Requirements - +12V Only in Section 3.2 of this document. When the voltage returns to within correct operating ranges and the fault is done, the signal will change to open (high impedance).

Support for this optional sideband signal does not rely on any of the other sideband signals defined for the 12VHPWR connector and can be implemented independently of other of these sideband signals.

3.3.3 CARD_CBL_PRES# (Optional)

This sideband signal has two functions:

- Primary Function:
 - This sideband signal provides a signal from the Add-in Card to the PSU that an Add-in Card has been detected and is correctly attached to the 12VHPWR Auxiliary Power Connector.
 - The primary function is required for all PCIe* Gen 5.0 Add-in Cards.
- Secondary Function:
 - This sideband signal provides communication from the Add-in Card to tell the PSU when an Add-in Card is present and can be included in the "Power Budgeting Sense Detect Registers". This allows the system to correlate which system and power cables are used with specific PCIe* card slot.

Note that this sideband signal is for the purpose of the system power supply management support. It is not for the purpose of the Add-in Card to determine the power limits available to it. Power limits to the Add-in Card are communicated by the SENSE0/SENSE1 signals.

The CARD_CBL_PRES# signal is tied to a $4.7k\Omega$ pull-down resistor to ground on the Add-in Cards. This signal is required for all PCIe* Gen 5.0 Add-in Cards, it will traverse the sideband signals of the 12VHPWR connector. If the PSU monitors the state of the CARD_CBL_PRES# signal, it must do so with a high impedance 3.3V logic compatible device input. This signal will be low at the Add-in Cards at all times with main power is absent. For a PSU to detect the active low presence condition of the CARD_CBL_PRES# signal a $100k\Omega$ pull-up resistor to 3.3V is required.

When supporting the secondary function, the Add-in Card reads this signal on a high impedance 3.3V logic compatible input and record the logic high/low state in the "Power Budgeting Sense Detect" registers. The PSU is allowed to drive this signal high with a push-pull driver to 3.3V.

Support for this optional sideband signal does not rely on any of the other sideband signals defined for the 12VHPWR connector and can be implemented independently of other of these sideband signals.

For a power supply this sideband signal can be used to determine how many PCIe* Add-in Cards are connected to the power supply. Then the power supply could determine how much power it can provide to each 12VHPWR connector via the SENSE



0/1 sideband signals. If this feature is used and the SENSE 0/1 signals are dynamically changed they must be changed only when the power supply is in Standby Mode (PS_ON# is de-asserted and Main Power rails are not on). Once PS_ON# and the main power rails achieve their full voltages the SENSE 0/1 sideband signals must not be changed.

An example for this scenario would be if a power supply has enough rated power to supply 600 Watts to one PCIe* Add-in Card it could determine the following scenarios:

- One PCIe* Add-in Card is detected, and that one card gets 600 Watt.
- Two PCIe* Add-in Cards are detected, each card gets 300 Watts.
- Three or Four PCIe* Add-in Cards are detected, each card gets 150 Watts.

3.3.4 Sideband Signals DC Specifications (Required)

The four sideband signals defined for the 12VHPWR connector DC Specifications are shown in <u>Table 3-7</u>. This is the requirement defined by the PCIe* CEM 5.0 Specification for the Add-in Cards.

Table 3-7: PCI Express* 12VHPWR Connector - Sideband Signal DC Specifications

Symbol	Parameter	Conditions	Min	Max
VHMAX	Max High Voltage any Pin			3.3 V +0.5 V
VIL	Input Low Voltage		-0.2 V	+0.8 V
VIH	Input High Voltage		+2.0 V	3.3 V +0.2 V
VoL	Output Low Voltage	7.0 mA	-0.2 V	+0.5 V
Voн	Output High Voltage (refer note)	4.0 mA	+2.4 V	3.3 V + 0.2 V
RPULL-UP	Pull-up / Pull-down Resistance tolerance		-10%	+10%

NOTE: For Open-Collector/Open Drain Signal CARD_PWR_STABLE output a pull-up is required. There is no VOH specification for this signal.

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4 Electrical

The following electrical requirements are required and must be met over the environmental ranges as defined in <u>Chapter 7</u> (unless otherwise noted).

4.1 AC Input - REQUIRED

Table 4-1 lists AC input voltage and frequency requirements for continuous operation. The power supply shall be capable of supplying full-rated output power over two input voltage ranges rated 90-135 VAC and 180-265 VAC rms nominal. The correct input range for use in a given environment may be either switch-selectable or auto-ranging. The power supply shall automatically recover from AC power loss. The power supply must be able to start up under full loading at 90 VAC.

Note: OPTIONAL - 115 VAC or 230 VAC only power supplies are an option for specific geographical or other requirements.

Table 4-1: AC Input Line Requirements

Parameter	Minimum	Nominal ¹	Maximum	Unit
Vin (115 VAC)	90	115	135	VAC _{rms}
Vin (230VAC)	180	230	265	VAC _{rms}
Vin Frequency	47	-	63	Hz

NOTE: Nominal voltages for test purposes are considered to be within ± 1.0 V of nominal.

4.1.1 Input Over Current Protection – REQUIRED

The power supply is required to incorporate primary fusing for input over current protection to prevent damage to the power supply and meet product safety requirements. Fuses should be slow-blow-type or equivalent to prevent nuisance trips.

4.1.2 Inrush Current - REQUIRED

Maximum inrush current from power-on (with power-on at any point on the AC sine) and including, but not limited to, three-line cycles, shall be limited to a level below the surge rating of the AC switch if present, bridge rectifier, and fuse components. Repetitive ON/OFF cycling of the AC input voltage should not damage the power supply or cause the input fuse to blow.

4.1.3 Input Under Voltage – REQUIRED

The power supply is required to contain protection circuitry such that the application of an input voltage below the minimum specified in <u>Table 4-1</u>, shall not cause damage to the power supply.



4.2 DC Output - REQUIRED

4.2.1 DC Voltage Regulation – REQUIRED

The DC output voltages are required to remain within the regulation ranges shown in $\frac{\text{Table 4-2}}{\text{Table 4-2}}$, when measured at the load end of the output connectors under all line, load, and environmental conditions specified in Chapter $\frac{7}{2}$.

The lower voltage range for 12V is allowed to be -7% to allow for the power excursion requirements now described in <u>Section 3.1</u>. To compensate for these power excursions the nominal voltage could be changed to 12.1 or 12.2 Volts, depending on Power Supply design.

Table 4-2: DC Output Voltage Regulation

Output	Range	Min	Nom	Max	Unit
+12V1DC ²	+5% / -7%	+11.20	+12.00	+12.60	V
+12V2DC ²	+5% / -7%	+11.20	+12.00	+12.60	V
+5VDC	±5%	+4.75	+5.00	+5.25	V
+3.3VDC	±5%	+3.14	+3.30	+3.47	V
-12VDC ³	±10%	-10.80	-12.00	-13.20	V
+5VSB	±5%	+4.75	+5.00	+5.25	V

NOTES:

- 1. Voltage tolerance is required at all connectors
- 2. +12V1DC and +12V2DC requirement applies to all +12V power rails
- 3. -12VDC output is optional

4.2.2 DC Output Current – REQUIRED

The below table summarizes the expected output transient step sizes for each output. All items in the below table are REQUIRED, unless specifically called out as RECOMMENDED.

Table 4-3: DC Output Transient Step Sizes

Output	Maximum Step Size (% of rated output amps)	Maximum Step Size (A)
+12V1DC ⁴	40% (Required) 70% (Recommended)	-
+12V2DC ⁴	85% of CPU supported in Table 2-1 ²	-
+12V3/4 ⁴	Steps from $100\% \to 300\%$ $30\% \to 100\%$ ³	
+5VDC	30%	-
+3.3VDC	30%	-



Output	Maximum Step Size (% of rated output amps)	Maximum Step Size (A)
-12VDC	-	0.1
+5VSB	-	0.5

NOTES:

- 1. Example of how to use this table, for a rated +5 VDC output of 14A, the transient step would be $30\% \times 14$ A = 4.2 A. Testing for a 4.2 A step size would result in testing starting at 9.8A going up to 14A.
- 2. 12V2 rails are typically used for CPU power. CPU step size will have more updated values in the Power Supply Design Guide Addendum (# 621484) which will be used to determine the 85% value
- 3. 12V3/V4 rails are typically used for PCIe* Add-in Card connectors. This recommendation is based on Chapter 3 where PCIe* Add-in Card needs are discussed. The step size will come from the amount of PCIe* Add-in Card power supported based on the size of the PSU in Table 3-2. For more detail reference the Desktop Platform Form Factor Power Supply Test Plan (Doc # 338448)
- 4. Power supplies that have one combined 12V rail shall perform Dynamic testing on the one 12V rail with multiple tests which simulate different system level workloads: 12V1 (total system), 12V2 (CPU Load), and 12V3/V4 (PCIe AIC).

Output voltages should remain within the regulation limits of $\underline{\text{Table 4-2}}$, for instantaneous changes in load as specified in $\underline{\text{Table 4-3}}$ and for the following conditions:

- Simultaneous load steps on the +12 VDC, +5 VDC, and +3.3 VDC outputs (all steps occurring in the same direction)
- Load-changing repetition rate of 50 Hz to 10 kHz
- AC input range per <u>Section 2.1</u> and Capacitive loading per <u>Table 4-7</u>

The transient load slew rate is defined in <u>Table 4-5</u> based on whether the PSU supports the PCIe* 12VHPWR Connectors. This usually can be correlated to the PSU's Rated Wattage, which is listed as a guidance.

Table 4-4: DC Output Transient Slew Rate

Output	PSU without PCIe* 12VHPWR Connectors (Rated Size ≤450 Watts)	PSU with PCIe* 12VHPWR Connector (Rated Size >450 Watts)
All +12V	2.5 A/µs	5.0 A/μs
+5V	1.0 A/µs	1.0 A/µs
+3.3V	1.0 A/µs	1.0 A/μs
+5VSB	0.1 A/μs	0.1 A/μs
-12V	0.1 A/μs	0.1 A/μs



4.2.3 Remote Sensing - RECOMMENDED

Remote sensing is recommended. Remote sensing can accurately control motherboard loads by adding it to the PSU connector. The +3.3 VDC output should have provisions for remote sensing to compensate for excessive cable drops. In low power PSU, remote sensing is recommended. The default sense should be connected to pin 13 of the main power connector. Refer <u>Figure 5-2</u>. The power supply should draw no more than 10 mA through the remote sense line to keep DC offset voltages to a minimum.

4.2.4 Other Low Power System Requirements

To help meet multiple world-wide Energy Regulations the +5VSB standby rail must meet the following efficiency as shown in <u>Table 4-5</u> which is measured with the main outputs off (PS_ON# high state). These World-Wide Energy Regulations and standards include: Blue Angel* system requirements, RAL-UZ 78, US Presidential executive order 13221, ENERGY STAR*, ErP Lot 6 requirements (2010 and 2013 levels), and 2014 ErP Lot 3 requirements. Additionally, if any Computers use an Alternative Low Power Mode (ALPM) then the +5VSB standby efficiency has similar requirements as shown below.

Table 4-5: Recommended Standby Rail DC and AC Power Efficiency

5VSB Load Target	5VSB Actual Load	Efficiency Target (both 115V and 230V input)	Remark
Max / Label	3.0A / Label	75%	Recommend
1.5	5 A	75%	REQUIRED ALPM and ErP Lot 3 2014
1.00 A		75%	Recommend
0.55 A		75%	REQUIRED ALPM and ErP* Lot 3 2014
90 mA		55%	Recommend
45 mA		45%	REQUIRED ErP* Lot 6 2013

4.2.5 Output Ripple Noise - REQUIRED

The output ripple and noise requirements listed in $\underline{\text{Table 4-6}}$ shall be met throughout the load ranges specified for the appropriate form factor and under all input voltage conditions as specified in $\underline{\text{Table 4-1}}$.

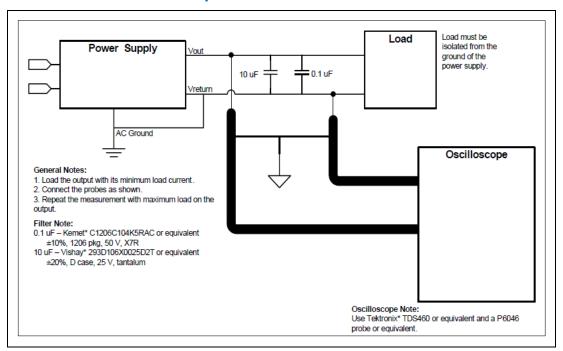
Ripple and noise are defined as periodic or random signals over a frequency band of 10 Hz to 20 MHz. Measurements shall be made with an oscilloscope with 20 MHz of bandwidth. Outputs should be bypassed at the connector with a $0.1\mu F$ ceramic disk capacitor and a $10~\mu F$ electrolytic capacitor to simulate system loading. Refer to Figure 4-1 for the differential noise measurement setup.



Table 4-6: DC Output Noise/Ripple

Output	Maximum Ripple and Noise (mV p-p)
+12V1DC	120
+12V2DC	120
+5VDC	50
+3.3VDC	50
-12VDC	120
+5VSB	50

Figure 4-1: Differential Noise Test Setup



4.2.6 Capacitive Load – RECOMMENDED

The power supply should be able to power up and operate within the regulation limits defined in <u>Table 4-2</u>, with the following capacitances simultaneously present on the DC outputs. These Capacitive Loads are to simulate what a motherboard / system provides when connected to a power supply.

Table 4-7: Output Capacitive Loads

Output	Capacitive Load (μF)
+12V1DC	3,300
+12V2DC	3,300



Output	Capacitive Load (μF)
+5VDC	3,300
+3.3VDC	3,300
-12VDC	330
+5VSB	3,300

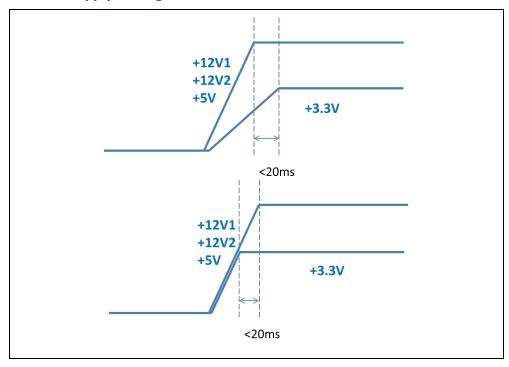
4.2.7 Closed Loop Stability - REQUIRED

The power supply shall be unconditionally stable under all line/load/transient load conditions including capacitive loads specified in <u>Section 4.2.6</u>. A minimum of 45 degrees phase margin and 10 dB gain margin is recommended at both the maximum and minimum loads.

4.2.8 +5V DC / +3.3V DC Power Sequencing - REQUIRED

The +12V1 DC / +12V2 DC and +5 VDC output levels must be equal to or greater than the +3.3 VDC output at all times during power-up and normal operation. The time between any output of +12V1 DC / +12V2 DC and +5 VDC reaching its minimum in-regulation level and +3.3 VDC reaching its minimum in-regulation level must be \leq 20 ms as shown in Figure 4-2.

Figure 4-2: Power Supply Timing





4.2.9 Voltage Hold-Up Time - REQUIRED

The power supply shall maintain output regulations per $\frac{\text{Table 4-2}}{\text{Table 4-2}}$ despite a loss of input power at the low-end nominal range-115 VAC / 47 Hz or 230 VAC / 47 Hz – at maximum continuous output load as applicable for a minimum of 17ms (T5+T6).

4.2.10 12V2 DC Minimum Loading - REQUIRED

The power supply +12 V2DC shall maintain output regulations per <u>Table 4-2</u> and meet minimum current values below.

Table 4-8: 12V2 DC Minimum Current

Output	Minimum current (A)
+12V2 DC	0A (Required)
+12V1 DC	0A (recommended)

4.3 Timing, Housekeeping and Control – REQUIRED

Figure 4-3: Power on Timing

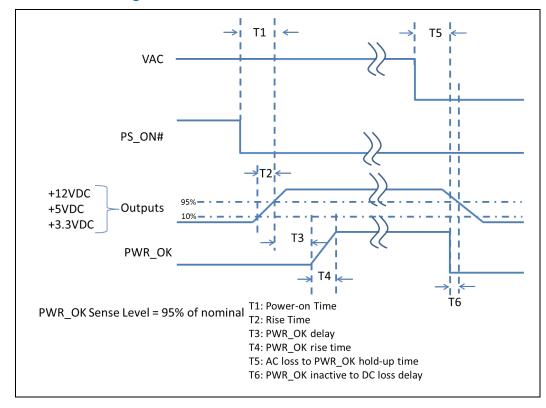




Table 4-9: Power Supply Timing

		Value					
Parameter	Description	Description Legacy Timings ¹ Required		Recommended for ALPM			
T0	AC power on time	-	<2s	-			
T1	Power-on time	< 500 ms	< 200 ms	<150 ms			
T2	Rise time	-	0.2 – 20 ms	-			
Т3	PWR_OK delay	100 ms ² – 500 ms	100 ms² – 250 ms	100 ms ² – 150 ms			
T4	PWR_OK rise time	-	< 10 ms	-			
Т5	AC loss to PWR_OK hold-up time ³	-	> 16 ms	-			
Т6	PWR_OK inactive to DC loss delay	-	> 1 ms	-			

- 1. Value in the Legacy column list timings for power supplies designed before the year 2020. In 2020, the T1 and T3 timings have moved from the Legacy timing to the new Required column for all new power supply designs.
- 2. T3 minimum time faster than 100 ms is not recommended for previous generation motherboards and systems. All design tolerances must be considered before allowing T3 faster than 100 ms.
 - a. A T3 time less than 100 ms may be designed based on system requirements and a need to provide faster PSU and system turn on capability. However, PSU and system designers are highly recommended to verify and ensure no PSU and system compatibility problems exist, especially for previous generation motherboards and systems.
- 3. T5 to be defined for both max/min load condition.
- 4. PSUs are recommended to label or indicate the timing value for system designer and integrator reference for T1 and T3. This allows system designers to optimize "turn on" time within the system.

4.3.1 PWR_OK - REQUIRED

PWR_OK is a "power good" signal. This signal shall be asserted high by the power supply to indicate that the +12 VDC, +5 VDC, and +3.3 VDC outputs are within the regulation thresholds listed in Table 4-2 and that sufficient mains energy is stored by the converter to guarantee continuous power operation within the specification for at least the duration specified in Section 4.2.9. Conversely, PWR_OK should be deasserted to a low state when any of the +12 VDC, +5 VDC, or +3.3 VDC output voltages fall below its voltage threshold, or when mains power has been removed for a time sufficiently long enough, such that power supply operation cannot be guaranteed. The electrical and timing characteristics of the PWR_OK signal are given in Table 4-10.

PSU manufacturers are required to label or tag PSU DG revision or ATX spec revision to show compliance and reflect the timing supported.



Signal Type	+5 V TTL compatible
Logic level low	< 0.4 V while sinking 4 mA
Logic level high	Between 2.4 V and 5 V output while sourcing 200 μA
High state output impedance	1 kΩ from output to common
Max Ripple/Noise	400 mV p-p

4.3.2 Power-Up Cross Loading Condition – REQUIRED

In the time frame between PS_ON# assertion and PWR_OK assertion (T1+T3), the power supply may be subjected to a cross load condition on the 12 V, 3.3 V and 5 V rails. The power supply must be able to successfully power up and assert PWR_OK when 12 V (or combination of 12V1 and 12V2) is loaded to \leq 0.1 A and 3.3 V and/or 5 V are loaded to 0-5 A.

4.3.3 PS ON# - REQUIRED

PS_ON# is an active-low, TTL-compatible signal that allows a motherboard to remotely control the power supply in conjunction with features such as soft on/off, Wake on LAN*, or wake-on-modem. When PS_ON# is pulled to TTL low, the power supply should turn on the four main DC output rails: +12 VDC, +5 VDC, +3.3 VDC, and -12 VDC. When PS_ON# is pulled to TTL high or open-circuited, the DC output rails shall not deliver current and must be held at zero potential with respect to ground. PS_ON# has no effect on the +5VSB output, which is always enabled whenever the AC power is present. To support systems with ALPM this is required for all power supplies. The power supply may be asked to turn back on before all voltage rails have turned off. The power supply must be able to turn back on via a change in the PS_ON# signal after 100 ms of the PS_ON# signal being de-asserted. Table 4-11 lists PS_ON# signal characteristics.

The power supply shall provide an internal pull-up to TTL high. The power supply shall also provide de-bounce circuitry on PS_ON# to prevent it from oscillating on/off at startup when activated by a mechanical switch. The DC output enable circuitry must be SELV-compliant.

The power supply shall not latch into a shutdown state when PS_ON# is driven active by pulses between 10 ms to 100 ms during the decay of the power rails. When PS_ON# de-asserts (turn on the PSU) with a time that is greater than 100 ms, from when it is first asserted (turns off), the PSU must respond to this request and turn back on all voltages rails no matter where the voltage rails are in ramping down the voltage to an Off state.

Table 4-11: PS_ON# Signal Characteristics

Parameter	Minimum	Maximum
V _{IL}	0	0.8 V
I_{IL} ($V_{IN} = 0.4 V$)	-	-1.6 mA¹
$V_{IH} (I_{IN} = 200 \text{ uA})$	2.0 V	-



Parameter	Minimum	Maximum
V _{IH} open circuit	-	-5.25 V
Ripple / Noise		400 mV p-p

NOTES:

- Negative current indicates that the current is flowing from the power supply to the motherboard.
- 2. Due to PS_ON# toggle on/off frequently, system and PSU component's reliability should be considered based on the days, months, or years of claimed warranty listed on product specification. Refer to Document #575961 PSU design consideration for S0ix mode.

Hysteresis = 0.3 V

= 0.8 V
PS is enabled

0.8 2.0 5.25 = Maximum Open Circuit Voltage

PS_ON# Voltage

Figure 4-4: PS_ON# Signal Characteristics

4.3.4 +5VSB - REQUIRED

+5VSB is a standby supply output that is active whenever the AC power is present. This output provides a power source for circuits that must remain operational when the five main DC output rails are in a disabled state. Example uses include soft power control, Wake on LAN, wake-on-modem, intrusion detection, Alternative Low Power Modes (ALPM) or suspend state activities.

The power supply must be able to provide the required power during a "wake up" event. If an external USB device generates the event, there may be peak currents as high as 3.5 A, lasting no more than 500ms.

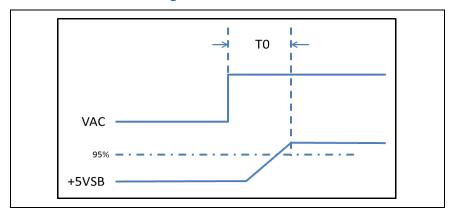
Over current protection is required on the +5VSB output regardless of the output current rating. This ensures the power supply will not be damaged if external circuits draw more current than the supply can provide.

With new modes of operation for computers like Alternative Low Power Modes (ALPM) the continuous current rating of the 5VSB rail is recommended to be at least 3 A.



Some scenarios like USB Power Charging in ALPM could require more current on the 5VSB rail.

Figure 4-5 +5VSB Power on timing versus VAC



4.3.5 Power-On Time – REQUIRED

The power-on time is defined as the time from when PS_ON# is pulled low to when the +12 VDC, +5 VDC, and +3.3 VDC outputs are within the regulation ranges specified in <u>Table 4-2</u>. The power-on time shall be less than 500 ms (T1 < 500 ms).

+5VSB shall have a power-on time of two second maximum after application of valid AC voltages as shown in <u>Figure 4-5</u>. The 5VSB power on time is T0 as listed in <u>Section 4.3.4</u>.

4.3.6 Rise Time – REQUIRED

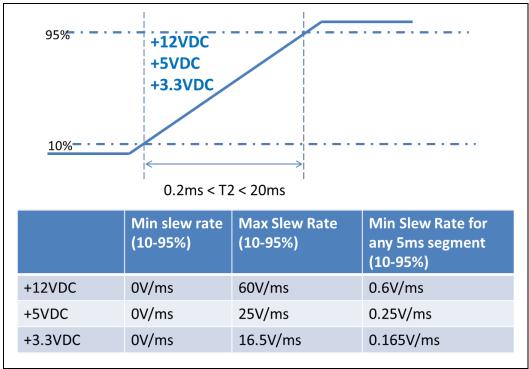
The output voltages shall rise from 10% of nominal to within the regulation ranges specified in <u>Table 4-2</u> within 0.2 ms to 20 ms (0.2 ms \leq T2 \leq 20 ms). The total time for Rise time of each voltage is listed in <u>Table 4-9</u> as T2.

There must be a smooth and continuous ramp of each DC output voltage from 10% to 95% of its final set point within the regulation band, while loaded as specified.

The smooth turn-on requires that, during the 10% to 95% portion of the rise time, the slope of the turn-on waveform must be positive and have a value of between 0 V/ms and [Vout, nominal / 0.2] V/ms. Also, for any 5 ms segment of the 10% to 95% rise time waveform, a straight line drawn between the end points of the waveform segment must have a slope \geq [Vout, nominal / 20] V/ms.



Figure 4-6: Rise Time Characteristics



4.3.7 Overshoot at Turn-On / Turn-Off – REQUIRED

The output voltage overshoot upon the application or removal of the input voltage, or the assertion/de-assertion of PS_ON#, under the conditions specified in <u>Table 4-2</u>, shall be less than 10% above the nominal voltage. No voltage of opposite polarity shall be present on any output during turn-on or turn-off.

4.4 Reset After Shutdown

If the power supply latches into a shutdown state because of a fault condition on its outputs, the power supply shall return to normal operation only after the fault has been removed and the PS_ON# has been cycled OFF/ON with a minimum OFF time of one second.

4.4.1 +5VSB at Power-Down - REQUIRED

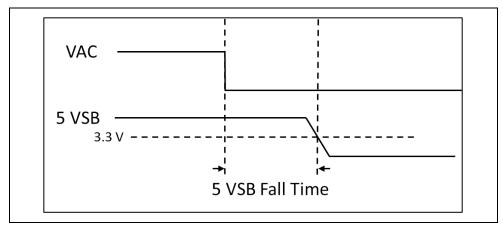
After AC power is removed, the +5VSB standby voltage output must remain at its steady state value for the minimum hold-up time specified in <u>Section 4.2.9</u> until the output begins to decrease in voltage. The decrease shall be monotonic in nature, dropping to 0.0 V. There shall be no other disturbances of this voltage at or following removal of AC power.



4.4.2 +5VSB Fall Time - RECOMMENDATION

Power supply 5VSB is recommended to go down to low level within 2 seconds under any load condition after AC power is removed as shown in Figure 4-7. Intel® test plan will test at Light 20% Load. If system requires specific +5VSB fall time, the PSU design is recommended to support it.

Figure 4-7: 5VSB Fall Time



4.5 Output Protection

4.5.1 Over Voltage Protection (OVP) – REQUIRED

The over voltage sense circuitry and reference shall reside in packages that are separate and distinct from the regulator control circuitry and reference. No single point fault shall be able to cause a sustained over voltage condition on any or all outputs. The supply shall provide latch-mode over voltage protection as defined in Table 4-12.

Table 4-12: Over Voltage Protection

Output	Minimum (V)	Nominal (V)	Maximum (V)
+12 VDC (or 12V1DC and 12V2DC)	13.4	15.0	15.6
+5VDC	5.74	6.3	7.0
+3.3VDC	3.76	4.2	4.3
+5VSB ¹	5.74	6.3	7.0

NOTE: Over voltage protection is RECOMMENDED but not REQUIRED for this output. While over voltage protection is not required for this output, system damage may occur in the case of an over voltage event.



4.5.2 Short Circuit Protection (SCP) – REQUIRED

An output short circuit is defined as any output impedance of less than 0.1 ohms. The power supply shall shut down and latch off for shorting the +3.3V DC, +5V DC, or +12V DC rails to return or any other rail. The +12V1 DC and 12V2 DC should have separate short circuit and over current protection. Shorts between main output rails and +5VSB shall not cause any damage to the power supply. The power supply shall either shut down and latch off or fold back for shorting the negative rails. +5VSB must be capable of being shorted indefinitely. When the short is removed, it is recommended that the power supply shall recover automatically or by cycling $PS_ON\#$. Optionally, the power supply may latch off when a +5VSB short circuit event occurs. The power supply shall be capable of withstanding a continuous short circuit to the output without damage or overstress to the unit (for example, to components, PCB traces, and connectors) under the input conditions specified in Table 4-1.

4.5.3 No-Load Situation – REQUIRED

Damage or hazardous condition shall not occur with all the DC output connectors disconnected from the load. The power supply may latch into the shutdown state.

4.5.4 Over Current Protection (OCP) – REQUIRED

Current protection must be designed to limit the current to operate within safe operating conditions.

Over current protection schemes, where only the voltage output that experiences the over current event is shut off, may be adequate to maintain safe operation of the power supply and the system; however, damage to the motherboard or other system components may occur. The recommended over current protection scheme is for the power supply to latch into the shutdown state. PSU connectors, cables and all other components should not be melted or damaged prior reaching to the OCP trigger.

4.5.5 Over Temperature Protection (OTP) – REQUIRED

The power supply shall include an over-temperature protection sensor, which can trip and shut down the power supply at a preset temperature point. Such an overheated condition is typically the result of internal current overloading or a cooling fan failure. If the protection circuit is non-latching, then it should have hysteresis built in to avoid intermittent tripping. PSU connectors, cables and all other components should not be melted or damaged prior reaching to the OCP trigger.

4.5.6 Output Bypass – REQUIRED

The output return may be connected to the power supply chassis and will be connected to the system chassis by the system components.

4.5.7 Separate Current Limit for 12V2 - OPTIONAL

The 12 V rail on the 2x2 power connector should be a separate current limited output to meet the requirements of UL and EN 62368-1. This only applies if the PSU is trying



to meet a 240VA Energy Hazard Safety Requirement, most power supplies are not currently designed to meet this requirement.

4.5.8 Overall Power Supply Efficiency Levels

The efficiency of the power supply should be tested at nominal input voltage of 115 VAC input and 230 VAC input, under the load conditions defined in the *Generalized Test Protocol for Calculating the Energy Efficiency of Internal Ac-Dc and Dc-Dc Power Supplies* document. This document defines how to determine full load criteria based on the label of each rail of the power supply. The loading condition for testing efficiency represents fully loaded systems, typical (50%) loaded systems, and light (20%) loaded systems.

The Efficiency requirements listed below are applicable to AC Input voltage of 115V.

Table 4-13: Efficiency versus Load Minimum Requirements

Loading	Full Load (100%)	Typical Load (50%)	Light Load (20%)
REQUIRED Minimum Efficiency	70%	72%	65%

Low Load Efficiency

Computers have decreased Idle power greatly since 2005, to where PSU loss is a big concern for overall AC power of a computer in Idle Mode. The lowest DC load for computers at this Idle Mode is determined to be 10 Watts for mainstream computers and could go lower. Computers with PSU larger than 500 Watts are also expected to have more components and therefore the Idle Mode will be at a higher DC Load. A PSU above 500 Watts will use the Low Load Efficiency set at the 2% level. The Low Load Efficiency requirements are shown in Table 4-14: Low Load Efficiency Requirements.

Table 4-14: Low Load Efficiency Requirements

Low Load Efficiency	10W / 2%
Required	60%
Recommended	70%

The 10-Watt load conditions are defined in the Desktop Platform Form Factors Power Supply Test Plan (#338448).



4.5.9 Power Supply Efficiency for Energy Regulations - ENERGY STAR* and CEC (California Energy Commission) PC Computers with High Expandability Score - RECOMMENDED

The efficiency of the power supply should be tested at nominal input voltage of 115 VAC input and 230 VAC input, under the load conditions defined in the form factor specific sections, and under the temperature and operating conditions defined in Chapter 7. The loading condition for testing efficiency represents fully loaded systems, typical (50%) loaded systems, and light (20%) loaded systems. For systems being sold into the state of California that meet the High Expandability Computer definition (details at the referenced CEC website below) are required to meet the efficiency target list in Table 4-16: Efficiency versus Load for CEC PC Computers with High Expandability Computers*.

Visit ENERGY STAR* Computers Ver.8 (ES v8) website for more details:

https://www.energystar.gov/products/spec/computers version 8 0 pd

Visit CEC* website for more details:

- https://www.energy.ca.gov/rules-and-regulations/appliance-efficiency-regulations-title-20 or
- https://energycodeace.com/content/reference-ace-t20-tool then select section "(v) Computers..."

Note: check ENERGY STAR* and CEC website for the latest specification update.

Table 4-15: Efficiency versus Load for ENERGY STAR*

Loading	Full Load (100%)	Typical Load (50%)	Light Load (20%)	PFC @ 50% load	Remarks
RECOMMENDED Minimum Efficiency	82%	85%	82%	≥0.9	ES v8 for 500W and below
RECOMMENDED Minimum Efficiency	87%	90%	87%	≥0.9	ES v8 for above 500W

Table 4-16: Efficiency versus Load for CEC PC Computers with High Expandability Computers*

Loading	Full Load (100%)	Typical Load (50%)	Light Load (20%)	PFC @ 50% load
REQUIRED Minimum Efficiency for 115V PSU	87%	90%	87%	≥0.9
REQUIRED Minimum Efficiency for 230V PSU	88%	92%	88%	≥0.9



*Details about High Expandability Computers definition check CEC computer regulation.

The RECOMMENDED minimum efficiency levels shown in $\underline{\text{Table 4-15}}$ are required for internal power supplies within the ENERGY STAR* for Computers Version 8.0 specification.

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5 Mechanical

This chapter contains mechanical guidelines that apply to desktop power supplies regardless of form factor. For form factor specific design guides refer to Chapter 11 through Chapter 16.

5.1 Labeling and Marking - RECOMMENDED

The following is a non-inclusive list of suggested markings for each power supply unit. Product regulation stipulations for sale into various geographies may impose additional labeling requirements.

Manufacturer information: manufacturer's name, part number and lot date code, etc., in human-readable text and/or bar code formats.

Nominal AC input operating voltages (100-127 VAC and 200-240 VAC) and current rating certified by all applicable safety agencies.

DC output voltages and current ratings.

Revision number of the ATX, SFX, etc. specification that the power supply meets.

Access warning text ("Do not remove this cover. Trained service personnel only. No user serviceable components inside.") must be in English, German, Spanish, French, Chinese, and Japanese with universal warning markings.

Power Supplies are recommended list the supported Required or Recommended **Timing values** (T1 and T3) in product documentation. There are two levels of timing for T1 and T3 a power supply can support as detailed in Figure 4-2. This will help system integrators and end users know the T1 and T3 timing values.

12VHPWR connector/cable harnesses that are hard-wired to the power supply shall be labeled indicating the **maximum power supported** according to the Sense0/1 encoding implemented for each connector. If the Sense lines are dynamic (can change in standby mode only), the product documentation must describe the power levels supported based on the number of PCIe* Add-in Cards connected. Sense0/1 are described in Section 3.3.1 of this document. An example of these labels are illustrated in Figure 5-1 below.

Figure 5-1: 12VHPWR Connector Labeling Example





5.2 Connectors - REQUIRED

5.2.1 AC Connector

The AC input receptacle must be an IEC 320 type or equivalent. In lieu of a dedicated switch, the IEC 320 receptacle may be considered the mains disconnect.

5.2.2 DC Connectors

<u>Table 5-1</u>: Main Power Connector Pin-Out shows pin outs and profiles for typical power supply DC harness connectors. The power supply requires an additional two-pin, power connector.

UL Listed or recognized component appliance wiring material rated min $85\,^{\circ}$ C, $300\,^{\circ}$ VDC shall be used for all output wiring.

There are no specific requirements for output wire harness lengths, as these are largely a function of the intended end-use chassis, motherboard, and peripherals. Ideally, wires should be short to minimize electrical/airflow impedance and simplify manufacturing, yet they should be long enough to make all necessary connections without any wire tension (which can cause disconnections during shipping and handling). The recommended minimum harness lengths for general-use power supplies is 150 mm for all wire harnesses. Measurements are made from the exit port of the power supply case to the wire side of the first connector on the harness.

+12V1 DC +3.3 VDC +3.3 VDC <u>Pin 1</u> +3.3 VDC -12 VDC +3.3 VDC +3.3 VDC COM COM +3.3 VDC COM COM +5 VDC PS ON# COM сом СОМ COM +5 VDC +5 VDC СОМ Peripheral СОМ СОМ +5 VDC Connector COM PWR_OK COM COM +12V1 DC +12V1 DC +12V1 DC +12V1 DC +3.3 VDC Main Power Connector Serial ATA Connector +12V2 DC Connector

Figure 5-2: Connectors (Pin-side view, not to Scale)

NOTE: Peripheral Connector is optional, does not show any PCIe* Add-in Card Connectors or 8 pin 12V2 connector.



5.2.2.1 Main Power Connector – REQUIRED

Connector: Molex* Housing: 24 Pin Molex Mini-Fit Jr. PN# 39-01-2240 or equivalent.

Contact: Molex 44476-1112 (HCS) or equivalent (Mating motherboard connector is Molex 44206-0007 or equivalent).

18 AWG is suggested for all wires except for the +3.3 V supply and sense return wires combined into pin 13 (22 AWG).

Table 5-1: Main Power Connector Pin-Out

Pin	Signal	Color	Pin	Signal	Color
1	+3.3V DC	Orange	13	+3.3V DC [+3.3 V default sense]	Orange [Brown]
2	+3.3V DC	Orange	14	-12V DC	Blue
3	СОМ	Black	15	СОМ	Black
4	+5V DC	Red	16	PS_ON#	Green
5	СОМ	Black	17	СОМ	Black
6	+5V DC	Red	18	СОМ	Black
7	СОМ	Black	19	СОМ	Black
8	PWR_OK	Gray	20	Reserved	NC
9	+5VSB	Purple	21	+5V DC	Red
10	+12V1 DC	Yellow	22	+5V DC	Red
11	+12V1 DC	Yellow	23	+5V DC	Red
12	+3.3V DC	Orange	24	СОМ	Black

5.2.2.2 Peripheral Connectors

Connector: AMP* 1-480424-0 or Molex* 15-24-4048 or equivalent.

Contacts: AMP 61314-1 or equivalent.



Table 5-2: Peripheral Connector Pin-out

Pin	Signal	Color ¹
1	+12V1 DC	Yellow
2	СОМ	Black
3	СОМ	Black
4	+5 VDC	Red

NOTE: 18 AWG wire.

5.2.2.3 Floppy Drive Connector – Do Not Include (For Historical Reference Only)

Connector: AMP* 171822-4 or equivalent.

Table 5-3: Floppy Connector Pin-out

Pin	Signal	Color ¹
1	+5V DC	Red
2	СОМ	Black
3	СОМ	Black
4	+12V1 DC	Yellow

NOTE: 20 AWG wire.

5.2.2.4 PCI-Express* (PCIe*) Add-in Card Connectors (Recommended)

These are optional connectors for the power supply to support additional power needed by any PCI Express** Add-in Card (AIC). The most common PCIe* Add-in Card that uses these connectors are discrete graphics cards. The PCIe* CEM Specification defines different connectors based on the power used by the Add-in Card which can range from 75 watts up to 600 watts.

5.2.2.4.1 PCI Express* (PCIe*) 2x3 Auxiliary Power Connector (Recommended)

The 2x3 Power Connector is designed to provide 75 watts to the PCIe* Add-in Cards and has the following requirements:

- Current Rating: 8.0 A/pin/position maximum to a 30 °C T-Rise above ambient temperature conditions at +12 VDC, all six contacts energized.
- Mated Connector Retention: 30.00 N minimum when plug pulled axially.

Cable Assembly Contact and Housing Details:

• Housing Material: Thermoplastic



- Pin Contact Base Material: Brass alloy or equivalent
- Pin Contact Plating: Sn alloy
- Flammability: UL94V-1 Minimum Material certification or certificate of compliance is required with each lot to satisfy the Underwriters Laboratories follow-up service requirements.
- Lead Free Soldering: Connector must be compatible with lead free soldering process

Table 5-4: PCIe* 2x3 Auxiliary Power Connector Pin Assignment (75 Watts)

Pin	Signal	Color ¹
1	+12V3/V4	Yellow
2	+12V3/V4	Yellow
3	+12V3/V4	Yellow

Pin	Signal	Color ¹	
4	СОМ	Black	
5	Sense	Black	
6	СОМ	Black	

NOTES:

1. Wire Size: 18 AWG

2. The Sense pin on the 2x3 auxiliary power connector must be connected to ground either directly in the power supply or via a jumper to an adjacent ground pin in the connector. This pin is used by a PCI Express* 2x3 150 W/225 W/300 W Add-in Card to detect whether the 2x3 auxiliary power connector is attached.

5.2.2.4.2 PCI Express* (PCIe*) 2x4 Auxiliary Power Connector (Recommended)

The 2x4 Auxiliary Power Connector consists of a *PCB_ Header*, mounted on a PCIe* Add-in Card, and a mating 2x4 *Cable Plug* harness. The 2x4 PCB header is designed to accept both the mating 2x4 Cable Plug as well as the 2x3 cable plug, for backward-compatibility. The Add-in Card PCB Header is keyed to ensure that a 2x3 cable plug from a PSU will be properly aligned when it is mated with a 2x4 PCB Header. Two Sense pins in the 2x4 PCB header allow the PCIe* Add-in Cards to detect the power available from the cable. The 2x4 Cable Plug asserts (grounds) two sense pins to indicate that 150 watts are available to the PCIe* Add-in Card through this cable, while the 2x3 plug asserts only one sense pin, to signal that only 75 W may be drawn from the cable. The 2x4 Cable Plug has the following requirements:

- Current Rating: 7.0 A per pin/position maximum to a 30°C T-Rise above ambient temperature conditions at +12 VDC with all eight contacts energized
- Mated Connector Retention: 30.00 N minimum when plug pulled axially

Cable Assembly Contact and Housing Details:

- Housing Material: Thermoplastic; Note that this connector has unique mechanical keying to avoid wrongful insertion of cable plug meant for different types of connectors.
- Pin Contact Base Material: Brass alloy or equivalent
- Pin Contact Plating: Sn alloy



- Flammability: UL94V-1 Minimum Material certification or certificate of compliance is required with each lot to satisfy the Underwriters Laboratories follow-up service requirements.
- Lead Free Soldering: Connector must be compatible with lead free soldering process

Table 5-5: PCIe* 2x4 Auxiliary Power Connector Pin Assignment (150 Watts)

Pin	Signal	Color ¹
1	+12V3/V4	Yellow
2	+12V3/V4	Yellow
3	+12V3/V4	Yellow
4	Sense1	Black

Pin	Signal	Color ¹
5	СОМ	Black
6	Sense0	Black
7	СОМ	Black
8	СОМ	Black

NOTE: 18 AWG wire.

Table 5-6: PCIe* 2x4 Auxiliary Power Connector Sense Pin Decoding by AIC

Sense 1	Sense 0	Description	
Ground	Ground	A 2x4 connector is plugged into the card. The card can draw up to 150 W from the auxiliary power connector	
Ground	Open	Reserved	
Open	Ground	A 2x3 connector is plugged into the card. The card can only draw up to 75 W from the auxiliary power connection	
Open	Open	No auxiliary power connector is plugged in	

For a sense pin that needs to be grounded, it must be connected to ground either directly in the power supply or via a jumper to an adjacent ground pin in the connector

5.2.2.4.3 PCI Express* (PCIe*) 12VHPWR Auxiliary Power Connector (Optional for PSU ≤ 450 Watts, Required for PSU > 450 Watts)

The 12VHPWR Auxiliary Power connector is designed to deliver up to 600 watts directly to a PCIe* Add-in Cards. This power connector is not compatible with the existing 2x3 or 2x4 auxiliary power connectors. The 12VHPWR connector power pins have a 3.0 mm spacing while the contacts in a 2x3 and 2x4 connector are on a larger 4.2 mm pitch. The 12VHPWR auxiliary power connector includes twelve large contacts to carry the power and four smaller contacts beneath carrying the sideband signals.

The connector performance requirements are as follows:

• Power Pin Current Rating: (Excluding sideband contacts) 9.2 A per pin/position with a limit of a 30 °C T-Rise above ambient temperature conditions at +12 VDC with all twelve contacts energized. The connector body must display a label or embossed H+ character to indicate support of 9.2 A/pin or greater. Refer for the approximate positioning of the marker on the 12VHPWR Right Angle (R/A) PCB Header.



• Mated Connector Latch Retention: 45.00 N minimum when plug pulled axially.

Figure 5-3: 12VHPWR Cable Plug Connector

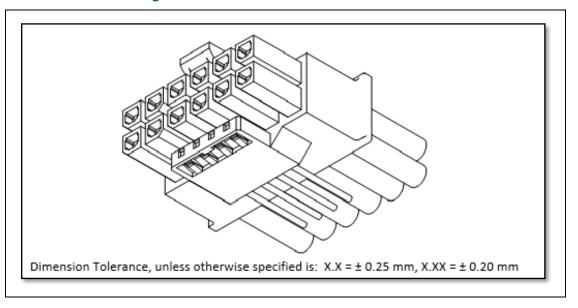
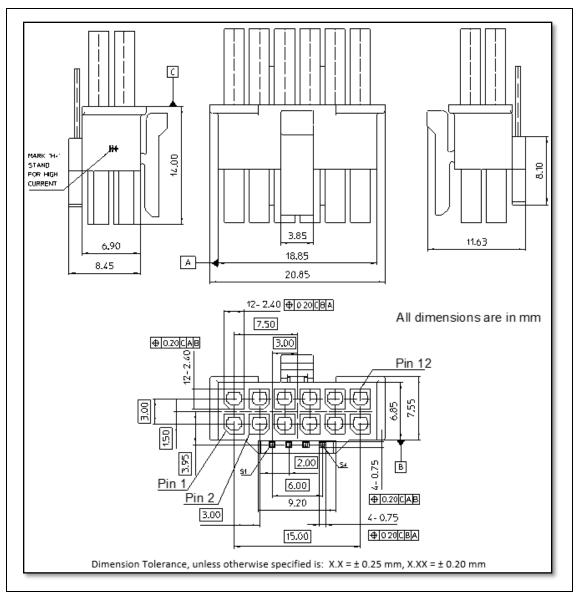




Figure 5-4: 12VHPWR Cable Assembly



The cable plug connector housing for the 12VHPWR connector has all dimensions shown in mm. Slight changes to this connector that does not affect matting with its associated plug may happen. Reference latest PCI-SIG documentation for latest information about this connector.

12VHPWR Cable Plug Assembly Contact and Housing Details:

- Housing Material: Thermoplastic Glass Fiber Filled, UL94V-0
- Color: Black
- Pin Contact Material: Copper Alloy
- Power Pin Contact Plating: Tin plated on contact area



- Signal Pin Contact Plating: Tin plated on contact area
- · All dimensions are in mm
- Connector must be compatible with lead-free soldering process.

Wire Details:

- Power/Ground Pin Wire Size: 16 AWG
 - All 12 pins must be connected to the power supply using 16 AWG cable
- Sideband Signals Pin Wire Size: 28 AWG

Table 5-7: PCIe* 12VHPWR Auxiliary Power Connector Pin Assignment (600 Watts)

Pin	Signal	Color ¹
1	+12V3/V4	Yellow
2	+12V3/V4	Yellow
3	+12V3/V4	Yellow
4	+12V3/V4	Yellow
5	+12V3/V4	Yellow
6	+12V3/V4 Yellow	
S1	CARD_PWR_STABLE	Blue
S2	CARD_CBL_PRES#	Blue

Pin	Signal	Color ¹
7	СОМ	Black
8	СОМ	Black
9	СОМ	Black
10	СОМ	Black
11	СОМ	Black
12	СОМ	Black
S3	SENSE0	Blue
S4	SENSE1	Blue

The electrical function for the sideband pins S1- S4 is detailed in $\underline{\text{Section 3.3}}$ of this document.

5.2.2.5 +12 V Power Connector

Connector: Molex* 0039012040 or equivalent.

Contact: Molex 44476-1112 (HCS) or equivalent (Mating motherboard connector is Molex 39-29-9042 or equivalent).

Table 5-8: +12 V Power 4 pin Connector Pin-out

Pin	Signal	Color ¹	Pin	Signal	Color ¹
1	СОМ	Black	3	+12V2 DC	Yellow
2	СОМ	Black	4	+12V2 DC	Yellow

NOTE: 18 AWG wire.



Table 5-9: +12 V Power 8 pin Connector Pin-Out

Pin	Signal	Color ¹	Pin	Signal	Color ¹
1	СОМ	Black	5	+12V2 DC	Yellow
2	СОМ	Black	6	+12V2 DC	Yellow
3	СОМ	Black	7	+12V2 DC	Yellow
4	СОМ	Black	8	+12V2 DC	Yellow

NOTE: 18 AWG wire.

5.2.2.6 Serial ATA* Connectors - REQUIRED

This is a required connector for systems with Serial ATA devices.

The detailed requirements for the Serial ATA Power Connector can be found in the "Serial ATA: High Speed Serialized AT Attachment" specification, Section 6.3 "Cables and connector specification".

http://www.serialata.org/

Note: Connector pin numbers and wire numbers are not 1:1. Carefully check to confirm the correct arrangement.

Assembly: Molex* 88751 or equivalent.

Table 5-10: Serial ATA* Power Connector Pin-out

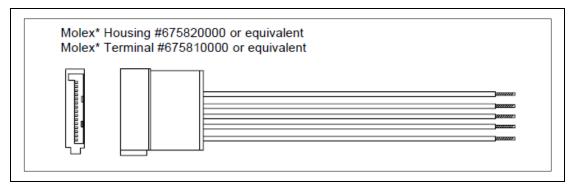
Wire	Signal	Color ¹
5	+3.3V DC	Orange ²
4	СОМ	Black
3	+5V DC	Red
2	СОМ	Black
1	+12V1 DC	Yellow

NOTES:

- 1. 18 AWG wire.
- 2. +3.3V DC is removed from SATA V3.2 spec. but it is recommended if there is backward compatibility concern.



Figure 5-5: Serial ATA* Power Connector



5.3 Airflow and Fans - RECOMMENDED

The designer's choice of a power supply cooling solution depends in part on the targeted end-use system application(s). At a minimum, the power supply design should ensure its own reliable and safe operation.

5.3.1 Fan Location and Direction

In general, exhausting air from the system chassis enclosure via a power supply fan at the rear panel is the preferred, most common, and most widely applicable system-level airflow solution. However, some system/chassis designers may choose to use other configurations to meet specific system cooling requirements.

5.3.2 Fan Size and Speed

A thermally sensitive fan speed control circuit is recommended to balance system-level thermal and acoustic performance. The circuit typically senses the temperature of the secondary heatsink and/or incoming ambient air and adjusts the fan speed as necessary to keep power supply and system component temperatures within specification. Both the power supply and system designers should be aware of the dependencies of the power supply and system temperatures on the control circuit response curve and fan size and should specify them carefully.

Fan should not turn on at the same time as PS_ON# is Asserted. This is because of power optimization at low levels and Alternative Low Power Modes. Two options to consider:

- 1. Wait for at least 2 seconds before the fan turns on.
- 2. Fan needs to be only turned on when the PSU needs the thermal cooling.

The power supply fan should be turned off when PS_ON# is de-asserted (high). In this state, any remaining active power supply circuitry must rely only on passive convection for cooling.



5.3.3 Venting

In general, more venting in a power supply case yields reduced airflow impedance and improved cooling performance. Intake and exhaust vents should be large, open, and unobstructed as possible so as not to impede airflow or generate excessive acoustic noise. In particular, avoid placing objects within 0.5 inches of the intake or exhaust of the fan itself. A flush-mount wire fan grill can be used instead of a stamped metal vent for improved airflow and reduced acoustic noise.

The limitations to the venting guidelines above are:

- Openings must be sufficiently designed to meet the safety requirements described in Chapter 9.
- Larger openings yield decreased EMI-shielding performance. Refer to Chapter 8.
- Venting in inappropriate locations can detrimentally allow airflow to bypass those areas where it is needed.

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6 Acoustics

6.1 Acoustics – RECOMMENDED

It is recommended that the power supply be designed with an appropriate fan, internal impedance, and fan speed control circuitry capable of meeting the acoustic targets listed in <u>Table 6-1</u>: Recommended Power Supply Acoustic Targets.

The power supply assembly should not produce, and prominent discrete tone determined according to ISO 7779, Annex D.

Sound power determination is to be performed at 43 C, at 50% of the maximum rated load, at sea level. This test point is chosen to represent the environment seen inside a typical system at the idle acoustic test condition, with the 43 C being derived from the standard ambient assumption of 23 C, with 20 C added for the temperature rise within the system (what is typically seen by the inlet fan). The declared sound power shall be measured according to ISO 7779 and reported according to ISO 9296.

Different customers might have different acoustic specifications. Any power supply design is recommended to follow any specific customer requirements.

Table 6-1: Recommended Power Supply Acoustic Targets

	Idle (BA)	Typical (50% load) (BA)	Maximum (BA)
Minimum	3.5	4.0	5.0
Target	3.0	3.8	4.5

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7 Environmental

The following subsections define environmental specifications and test parameters, based on the typical conditions to which a power supply may be subjected during operation or shipment.

7.1 Temperature – RECOMMENDED

- Operating ambient +10 °C to +50 °C (At full load, with a maximum temperature rate of change of 5 °C/10 minutes, but no more than 10 °C/hr.)
- Non-operating ambient -40 °C to +70 °C (Maximum temperature rate of change of 20 °C/hr.)

7.2 Thermal Shock (Shipping) - RECOMMENDED

- Non-operating -40 °C to +70 °C
- 15 °C/min \leq dT/dt \leq 30 °C/min
- Tested for 50 cycles; Duration of exposure to temperature extremes for each half cycle shall be 30 minutes.

7.3 Humidity - RECOMMENDED

- Operating To 85% relative humidity (non-condensing)
- Non-operating to 95% relative humidity (non-condensing)
- Note: 95% relative humidity is achieved with a dry bulb temperature of 55 °C and a wet bulb temperature of 54 °C.

7.4 Altitude – RECOMMENDED

- Operating to 10,000 ft.
- Non-operating to 50,000 ft.

7.5 Mechanical Shock – RECOMMENDED

- Non-operating 50 g, trapezoidal input; velocity change ≥ 170 in/s
- Three drops on each of six faces are applied to each sample.



7.6 Random Vibration – RECOMMENDED

• Non-operating 0.01 g²/Hz at 5 Hz, sloping to 0.02 g²/Hz at 20 Hz, and maintaining 0.02 g²/Hz from 20 Hz to 500 Hz. The area under the PSD curve is 3.13 gRMS. The duration shall be 10 minutes per axis for all three axes on all samples.

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8 Electromagnetic Compatibility

The following subsections outline applicable product regulatory requirements for the power supplies. Additional requirements may apply dependent upon the design, product end use, target geography, and other variables.

8.1 Emissions – REQUIRED

The power supply shall comply with FCC Part 15, EN55023 and CISPR 22, 5th ed., meeting Class B for both conducted and radiated emissions with a 4 dB margin. Tests shall be conducted using a shielded DC output cable to a shielded load. The load shall be adjusted as follows for three tests: No load on each output; 50% load on each output; 100% load on each output. Tests will be performed at 100 VAC 50Hz, 120 VAC 60 Hz, and 230 VAC 50 Hz power. Additionally, for FCC certification purposes, the power supply shall be tested using the methods in 47 CFR 15.32(b) and authorized under the Declaration of Conformity process as defined in 47 CFR 2.906 using the process in 47 CFR 2.1071 through 47 CFR 2.1077.

8.2 Immunity - REQUIRED

The power supply shall comply with EN 55024 and CISPR 24 prior to sale in the EU (European Union), Korea, and possibly other geographies.

8.3 Input Line Current Harmonic Content - OPTIONAL

Class D harmonic limits will be determined at the time of measurement based on the actual power draw from the mains.

<u>Table 8-1</u> is a partial list of countries and their current EMC requirements. Additional requirements may apply dependent upon the design, product end use, target geography, and other variables.

Table 8-1: EMC Requirement by Countr	Table 8-1	: EMC Rec	uirement	bv	Country
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Country	Requirements Document		
EU (European Union)	EN61000-3-2		
Japan	JEIDA MITI		
China	CCC and GB 17625.1		
Russia	GOST R 51317.3.2		

8.4 Magnetic Leakage Field - REQUIRED

A PFC choke magnetic leakage field must not cause any interference with a high-resolution computer monitor placed next to or on top of the end-use chassis.



8.5 Voltage Fluctuations and Flicker – REQUIRED

The power supply shall meet the specified limits of EN61000-3-3 (IEC 61000-3-3) and amendment A1 to EN 61000-3-3 (IEC 61000-3-3/A1) for voltage fluctuations and flicker for equipment drawing not more than 16VAC, connected to low voltage distribution systems.

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9 Safety

The following subsections outline sample product regulations requirements for a typical power supply. Actual requirements will depend on the design, product end use, target geography, and other variables. Consult your company's Product Safety and Regulations department or an accredited third-party certification agency for more details.

9.1 North America – REQUIRED

The power supply must be certified by an NRTL (Nationally Recognized Testing Laboratory) for use in the USA and Canada under the following conditions:

- The power supply UL report "Conditions of Acceptability" shall meet in the intended application of the power supply in the end product.
- The supply must be recognized for use in Information Technology Equipment including Electrical Business Equipment per UL 60950-1 First Edition. The certification must include external enclosure testing for the AC receptacle side of the power supply.
- The supply must have a full complement of tests conducted as part of the certification, such as input current, leakage current, hi-pot, temperature, energy discharge test, transformer output characterization test (open-circuit voltage, shortcircuit performance), and abnormal testing (to include stalled-fan tests and voltageselect-switch mismatch).
- The enclosure must meet fire enclosure mechanical test requirements per clauses 2.9.1 and 4.2 of the above-mentioned standard.
- Production hi-pot testing must be included as a part of the certification and indicated as such in the certification report.
- There must not be unusual or difficult conditions of acceptability such as mandatory additional cooling or power de-rating. The insulation system shall not have temperatures exceeding their rating when tested in the end product.
- The certification mark shall be marked on each power supply.
- The power supply must be evaluated for operator-accessible secondary outputs (reinforced insulation) that meet the requirements for SELV.
- The proper polarity between the AC input receptacle and any printed wiring boards connections must be maintained (that is, brown=line, blue=neutral, and green=earth/chassis).
- The fan shall be protected by a guard to prevent contact by a finger in compliance with UL accessibility requirements.

9.2 International – REQUIRED

The vendor must provide a complete CB certificate and test report to IEC 60950-1. The CB report must include ALL CB member country national deviations as appropriate for the target market. All evaluations and certifications must be for reinforced insulation between primary and secondary circuits.



The power supply must meet the RoHS requirements for the European Union, Peoples Republic of China and other countries which have adopted the RoHS requirements for banned materials.

9.3 Proscribed Materials - REQUIRED

The following materials must not be used during design and/or manufacturing of this product:

- Cadmium shall not be used in painting or plating REQUIRED.
- Quaternary salt and PCB electrolytic capacitors shall not be used REQUIRED.
- CFC's or HFC's shall not be used in the design or manufacturing process -REQUIRED.
- Mercury shall not be used REQUIRED.
- Some geographies require lead free or RoHS compliant power supplies REQUIRED.

9.4 Catastrophic Failure Protection - RECOMMENDED

Should a component failure occur, the power supply should not exhibit any of the following:

- Flame
- Excessive smoke
- Charred PCB
- · Fused PCB conductor
- Startling noise
- · Emission of molten material
- Earth ground fault (short circuit to ground or chassis enclosure)

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10 Reliability

10.1 Reliability - RECOMMENDED

The de-rating process promotes quality and high reliability. All electronic components should be designed with conservative device de-ratings for use in commercial and industrial environments.

Electrolytic capacitor and fan lifetime and reliability should be considered in the design as well.

10.2 Reliability – PS_ON# toggle for S0ix mode - REQUIRED

In order to optimize desktop platform power consumption, Intel provides design recommendation to enable PSU PS_ON# toggle on/off during S0 idle power mode (S0ix) to save both system and PSU power. The PSU PS_ON# may toggle on/off every 180s (PSU to be on for 1s and off for 180s) when customer desktop designs implement S0 idle which is different from the legacy desktop platform design that PS_ON# only toggle once when turn on. The S0ix mode is used in systems that use Alternative Low Power Modes.

If the computer turns on/off every 180 seconds the worse case scenario would be 480 times in one day and 175,200 times in one year. The power supply needs to be able to handle these many cycles for the life of the power supply.

To have better user's experience and avoid PSU fan acoustic noise annoyance, system and PSU designers shall have at least two seconds delay time for the PSU fan to spin up after PS_ON# assertion. PSU is expected to support running at full load without any electrical, thermal components (i.e., IC, MOSFET, diode, transformer, inductor, capacitor, relay, fan, etc.) damaged or degradations during the period of time before the warranty expired. Due to the frequent PS_ON# toggle on/off, system and PSU component's reliability should be considered based on the days, months, or years of claimed warranty listed on product specification. This is also mentioned in Section 5.3.2.

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11 CFX12V Specific Guidelines 2.0

For Compact Form Factor with 12-volt connector power supplies.

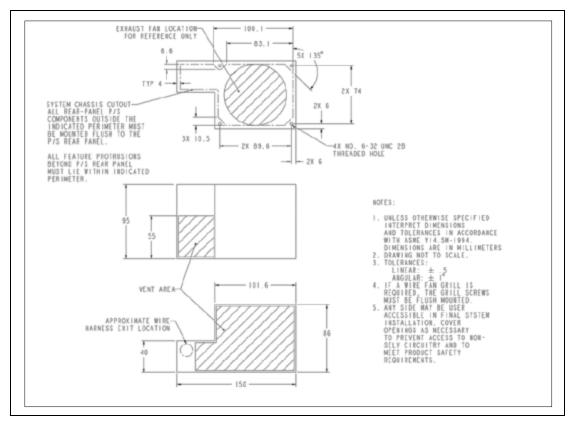
All Form Factors Revision Summary:

PSU DG	CFX12V	LFX12V	ATX12V	SFX12V	TFX12V	Flex ATX
2.0	2.0	2.0	3.0	4.0	3.0	2.0

11.1 Physical Dimensions – REQUIRED

The power supply shall be enclosed and meet the physical outline shown.

Figure 11-1: CFX12V Mechanical Outline



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12 LFX12V Specific Guidelines 2.0

For Low Profile Form Factor with 12-volt connector power supplies.

All Form Factors Revision Summary:

PSU DG	CFX12V	LFX12V	ATX12V	SFX12V	TFX12V	Flex ATX
2.0	2.0	2.0	3.0	4.0	3.0	2.0

12.1 Physical Dimensions - REQUIRED

The power supply shall be enclosed and meet the physical outline shown in <u>Figure 12-1</u>, applicable. Mechanical details are shown in <u>Figure 12-2</u>. Details on the power supply slot feature are shown in <u>Figure 12-3</u>. The recommended chassis slot feature details are shown in <u>Figure 12-4</u>.

Figure 12-1: LFX 12V Mechanical Outline

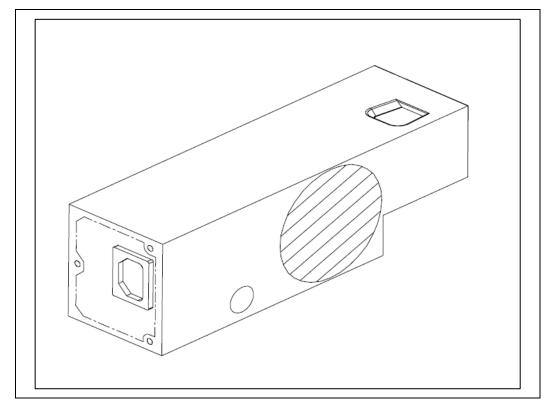




Figure 12-2: Mechanical Details

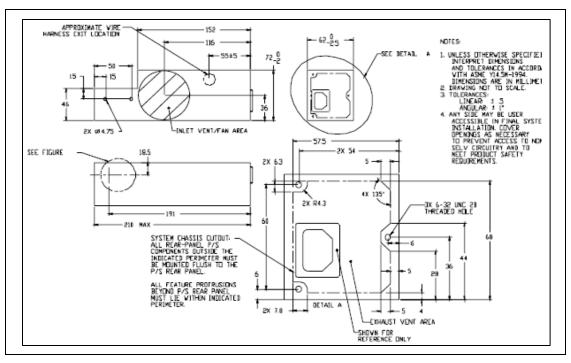




Figure 12-3: PSU Slot Feature Detail

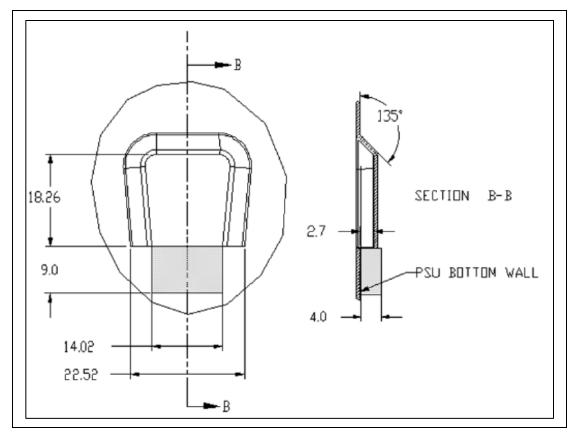
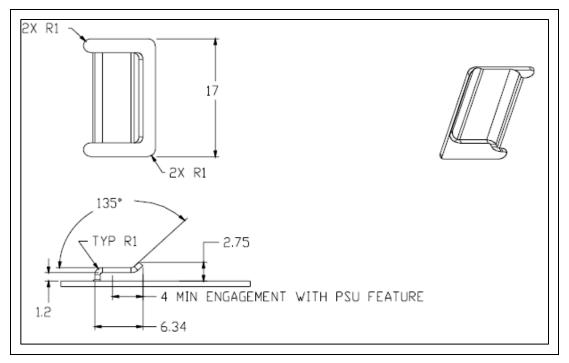




Figure 12-4: Recommended Chassis Tab Feature



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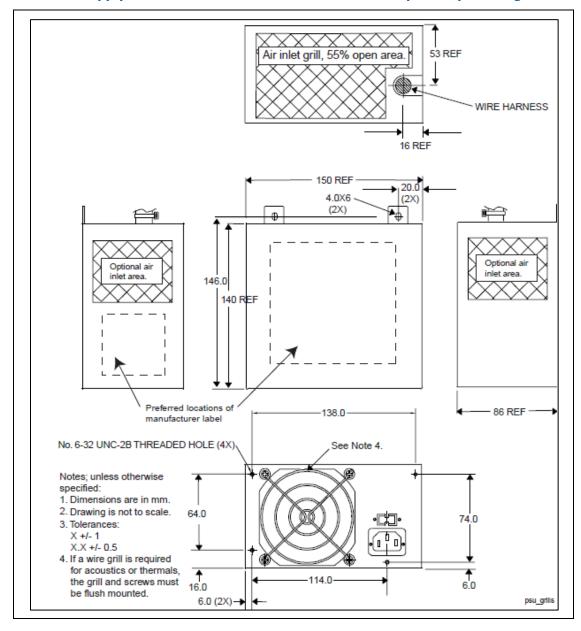
13 ATX12V Specific Guidelines 3.0

For ATX Form Factor with 12-volt connector power supplies.

All Form Factors Revision Summary:

PSU DG	CFX12V	LFX12V	ATX12V	SFX12V	TFX12V	Flex ATX
2.0	2.0	2.0	3.0	4.0	3.0	2.0

Figure 13-1: Power Supply Dimensions for Chassis that does not Require Top Venting





53 REF WIRE HARNESS 11.0 x 5.0 cutouts (4X); 16 REF min 6.0 clearance under cutout from inside top cover. 150 REF **≯**₁20.0 4.0X6-(2X) See Note 5. 94.0 Area on top surface inside dotted lines should 146.0 have 60% minimum open Preferred location of area for proper venting. manufacturer label 80.0 140 RÉP. Eight rectangular holes are for air duct mounting to direct airflow across 5,0 processor heatsink. 8.0 -114.0 138.0 No. 6-32 UNC-2B THREADED HOLE (4X) 86 REF 9.0 x 3.2 cutouts (4X); Notes; unless otherwise specified: See Note 4. min 5.0 clearance under 1. Dimensions are in mm. cutout from inside top cover. Drawing is not to scale. 3. Tolerances: X +/- 1 X.X +/- 0.5 4. If a wire grill is required 64.0 for acoustics or thermals, 74.0 the grill and screws must be flush mounted. Bottom side (not pictured) may be user-accessible in final system installation. 114.0 6.0 Cover openings as 16.0 necessary to prevent 6.0 (2X)→ access to non-SELV circuitry and to meet product psu_duct_mount safety requirements.

Figure 13-2: Power Supply Dimensions for Chassis that Require Top Venting



14 SFX12V Specific Guidelines 4.0

For Small Form Factor with 12-volt connector power supplies.

All Form Factors Revision Summary:

PSU DG	CFX12V	LFX12V	ATX12V	SFX12V	TFX12V	Flex ATX
2.0	2.0	2.0	3.0	4.0	3.0	2.0

14.1 Lower Profile Package - Physical Dimensions - REQUIRED

The power supply shall be enclosed and meet the physical outline shown in <u>Figure 14-1</u>.

14.2 Fan Requirements - REQUIRED

The fan will draw air from the computer system cavity pressurizing the power supply enclosure. The power supply enclosure shall exhaust the air through a grill located on the rear panel. Refer to <u>Figure 14-2</u>. The movement of the fan to the computer system cavity is to help limit the acoustic noise of the unit.

The fan will be 40 mm.



Figure 14-1: 40 mm Profile Mechanical Outline

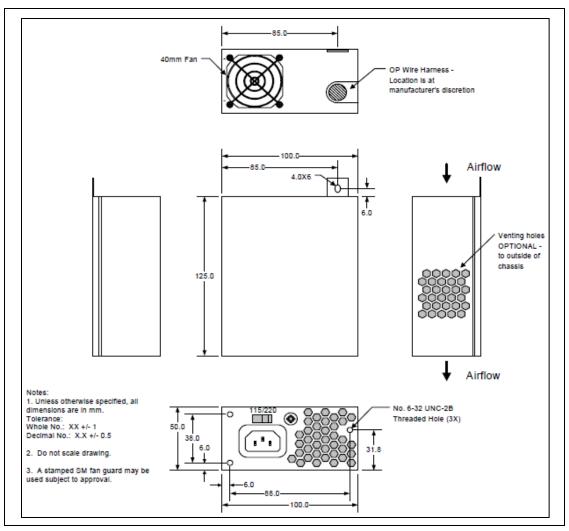
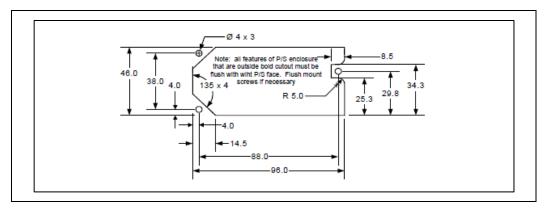


Figure 14-2: Chassis Cutout





14.3 Top Fan Mount Package - Physical Dimensions - REQUIRED

The power supply shall be enclosed and meet the physical outline shown in $\underline{\text{Figure}}$ $\underline{14-3}$.

14.4 Fan Requirements - REQUIRED

The fan will draw air from the computer system cavity pressurizing the power supply enclosure. The power supply enclosure shall exhaust the air through a grill located on the rear panel. Refer to Figure 14-4. Moving the fan to the computer system cavity helps to limit the acoustic noise of the unit.

The fan will be 80mm.

To prevent damage to the fan during shipment and handling, the power supply designer should consider recessing the fan mounting, as shown in <u>Figure 14-5</u>.



OP Wire Harness-Location is at manufacturer's discretion 11.0 X 5.0 cutout clearance under cutout minimum of 6.0 from -4.0X6 inside cover 0/ **⊢15.0** 12.0 95.8 125.0 Airflow 9.0 X 3.2 cutout Airflow clearance under cutout minimum of 4.5 from inside cover No. 6-32 UNC-2B 115/220 Threaded Hole (3X) **③** 51.5 6.0 -6.0 -88.0--100.0-

Figure 14-3: Top Mount Fan Profile Mechanical Outline



Figure 14-4: Chassis Cutout

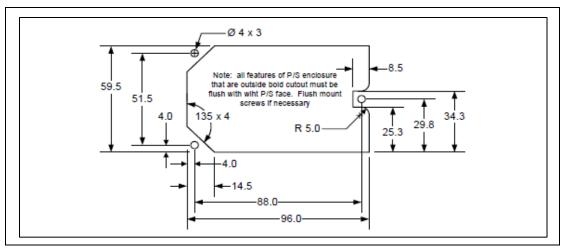
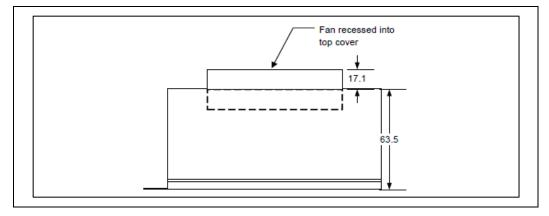


Figure 14-5: Recessed Fan Mounting



14.5 Reduced Depth Top Mount Fan - Physical Dimensions - REQUIRED

The power supply shall be enclosed and meet the physical outline shown in <u>Figure 14-6</u>.

14.6 Fan Requirements - REQUIRED

The fan will draw air from the computer system cavity pressurizing the power supply enclosure. The power supply enclosure shall exhaust the air through a grill located on the rear panel. Refer to Figure 14-7. Moving the fan to the computer system cavity helps to limit the acoustic noise of the unit.

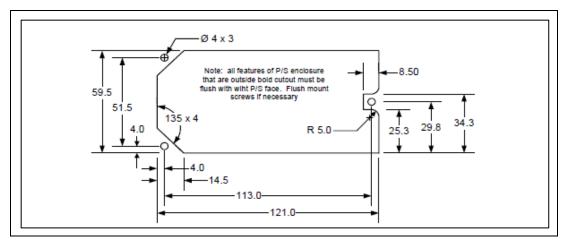
The fan will be 80 mm.



125.0-OP Wire Hamess -Location is at manufacturer's Mounting Tab Optional 11.0 X 5.0 cutout clearance under cutout minimum of 6.0 from 9.0 X 3.2 cutout clearance under cutout minimum of 4.5 from 0 Inside cover Airflow Airflow Notes:
1. Unless otherwise specified, all dimensions are in mm.
Tolerance:
Whole No.: XX +/- 1
Decimal No.: X.X +/- 0.5 No. 6-32 UNC-2B Threaded Hole (3X) 115/220 A stamped SM fan guard may be used subject to approval. AC Input Connector --6.0 Location is at manufacturer's discretion

Figure 14-6: Reduced Depth Top Mount Fan Profile Mechanical Outline

Figure 14-7: Chassis Cutout





14.7 Standard SFX Profile Package - Physical Dimensions - REQUIRED

The power supply shall be enclosed and meet the physical outline shown in <u>Figure 14-8</u>.

14.8 Fan Requirements - REQUIRED

The fan will draw air from the computer system cavity pressurizing the power supply enclosure. The power supply enclosure shall exhaust the air through a grill located on the rear panel. Refer to <u>Figure 14-9</u>. The movement of the fan to the computer system cavity is to help limit the acoustic noise of the unit.

The fan will be 60 mm.

Figure 14-8: 60 mm Mechanical Outline

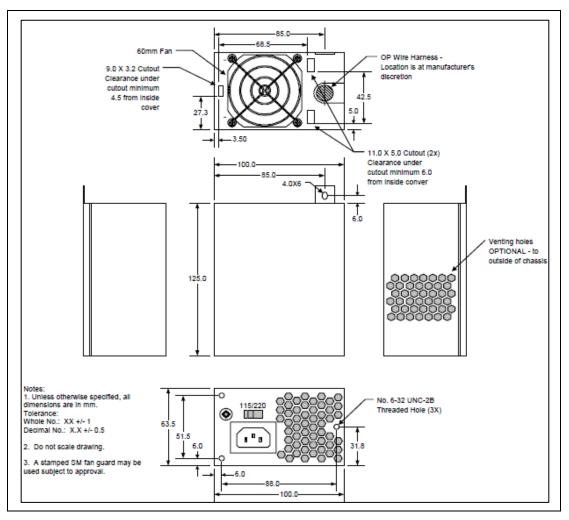
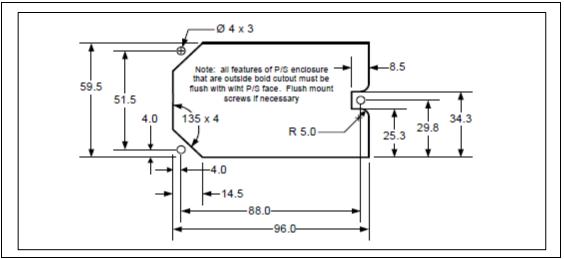




Figure 14-9: Chassis Cutout



14.9 PS3 Form Factor-Physical Dimensions - REQUIRED

The power supply shall be enclosed and meet the physical outline shown in $\underline{\text{Figure}}$ $\underline{14-10}$.

14.10 Fan Requirements - REQUIRED

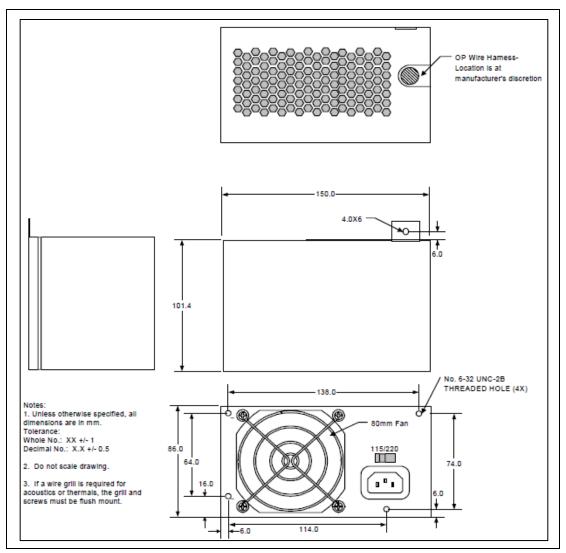
An 80 mm axial fan is typically needed to provide enough cooling airflow through a high performance Micro ATX system. Exact CFM requirements vary by application and endues environment, but 25-35 CFM is typical for the fan itself.

For consumer or other noise-sensitive applications, it is recommended that a thermally sensitive fan speed control circuit be used to balance system-level thermal and acoustic performance. The circuit typically senses the temperature of an internal heatsink and/or incoming ambient air and adjusts the fan speed as necessary to keep power supply and system component temperatures within specification. Both the power supply and system designers should be aware of the dependencies of the power supply and system temperatures on the control circuit response curve and fan size and should specify them very carefully.

The power supply fan shall be turned off when PS_ON# is de-asserted (high). In this state, any remaining active power supply circuitry must rely only on passive convection for cooling.



Figure 14-10: PS3 Mechanical Outline



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15 TFX12V Specific Guidelines 3.0

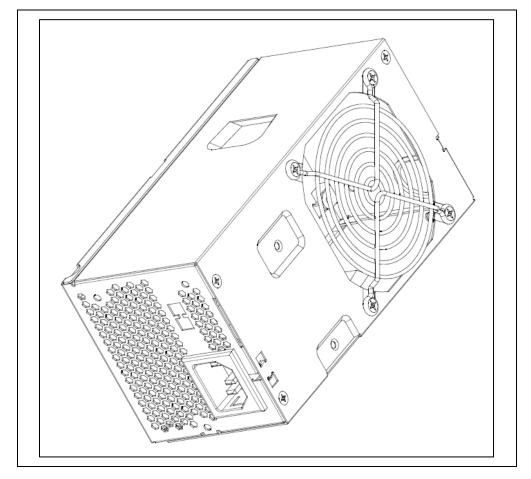
For Thin Form Factor with 12-volt connector power supplies.

All Form Factors Revision Summary:

PSU DG	CFX12V	LFX12V	ATX12V	SFX12V	TFX12V	Flex ATX
2.0	2.0	2.0	3.0	4.0	3.0	2.0

15.1 Physical Dimensions - REQUIRED

Figure 15-1: Mechanical Outline





Ĭ 6-32 UNC 2-B T 2 PLACES • A PUNCHED FAN GUARD IN THE CASE MAY BE USED IN PLACE OF THE WIRE FAN GUARD 0 ធែ១⊛

Figure 15-2: Dimensions and Recommended Feature Placements (not to scale)



DETAIL SCALE

Figure 15-3: Power Supply Mounting Slot Detail

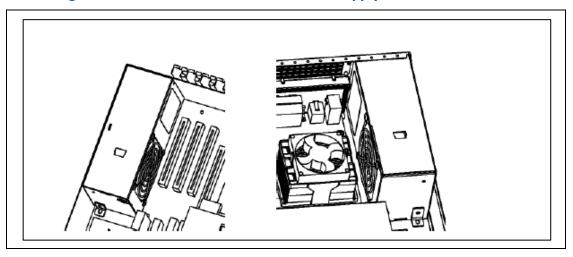
15.2 Mounting Options - RECOMMENDED

The TFX12V mechanical design provides two options for mounting in a system chassis. The unit can be mounted using one of the mounting holes on the front end (nonvented end) or a chassis feature can be designed to engage the slot provided in the bottom of the supply. In order to accommodate different system chassis layouts, the TFX12V power supply is also designed to mount in two orientations (fan left and fan right) as shown in Figure 15-4. A mounting hole and slot should be provided for each



orientation as shown in <u>Figure 15-2</u>. Details of a suggested geometry for the mounting slot are shown in <u>Figure 15-3</u>.

Figure 15-4: Fan Right and Fan Left Orientations of Power Supply in a Chassis



15.3 Chassis Requirements - RECOMMENDED

To ensure the power supply can be easily integrated, the following features should be designed into a chassis intended to use a TFX12V power supply:

- Chassis cutout (normally in the rear panel of the chassis) as shown in Figure 15-5.
- EITHER a mounting bracket to interface with the forward mounting hole on the power supply OR a mounting tab as shown in Figure 15-6 to interface with the mounting slot on the bottom of the power supply.

Figure 15-5: Suggested TFX12V Chassis Cutout

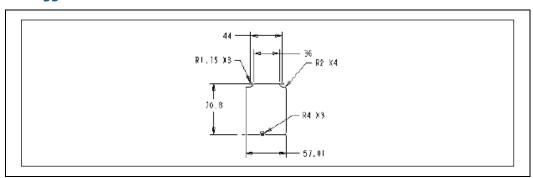
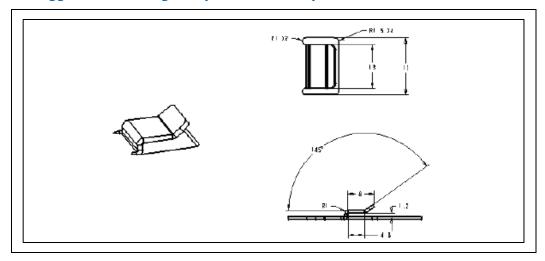




Figure 15-6: Suggested Mounting Tab (chassis feature)



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16 Flex ATX Specific Guidelines2.0

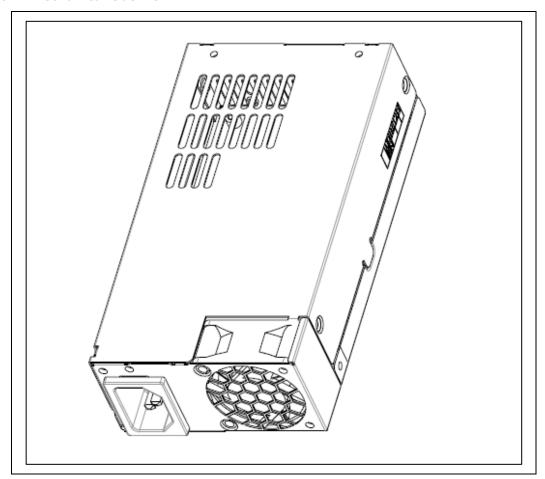
For Flex ATX Form Factor with 12-volt connector power supplies.

All Form Factors Revision Summary:

PSU DG	CFX12V	LFX12V	ATX12V	SFX12V	TFX12V	Flex ATX
2.0	2.0	2.0	3.0	4.0	3.0	2.0

16.1 Physical Dimensions – REQUIRED

Figure 16-1: Mechanical Outline





FLEX ATX A1 FLEX ATX 6-32 UNC-2B — 2 PLACES CABLE OUTLET MAY EXIST IN EITHER LOCATION PREFERRED MFG LABEL LOCATION 6-32 UNC-2B -4 PLACES

Figure 16-2: Dimensions and Recommended Feature Placements (not to scale)

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